

VULQ1-M from QiOVA

Accelerating ultrafast laser processing x10
with dynamically programmable
multibeam technology



Agenda

- QiOVA[®] at a glance
- Multibeam laser processing
- VULQ1 offering
- Examples of ACCELERATION with VULQ1-M



Qiova at a glance



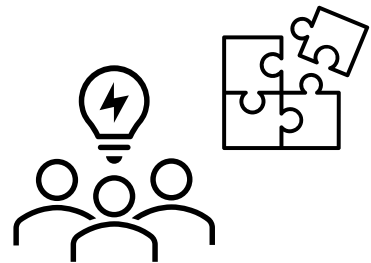
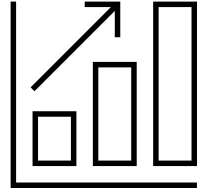
Pioneers of multibeam laser processing for industry

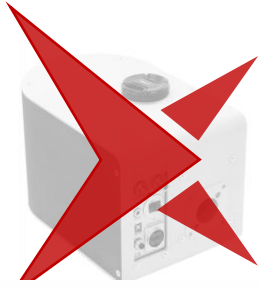




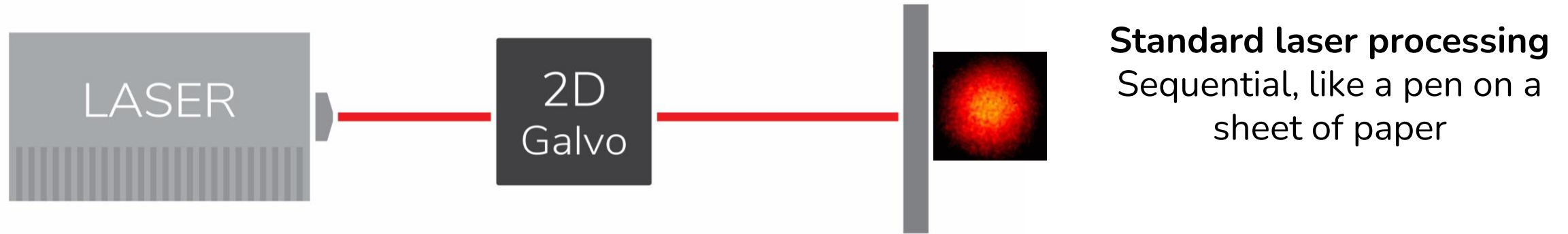
Latest news 2024

- Serie A funding – 2M€+ to accelerate market penetration
 - Led by top french Luxe industrial group
- >1 M€ booking by May
 - Pharmaceuticals and luxe sectors leading, marking systems driven
 - Electronics and industrial goods to follow
- x3 revenue in FY2024 vs FY2023
- Consolidating team with 8 new hires



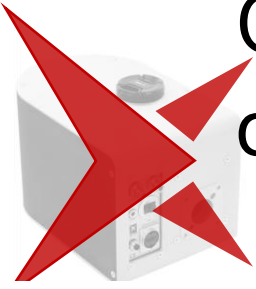


Current bottlenecks in laser processing

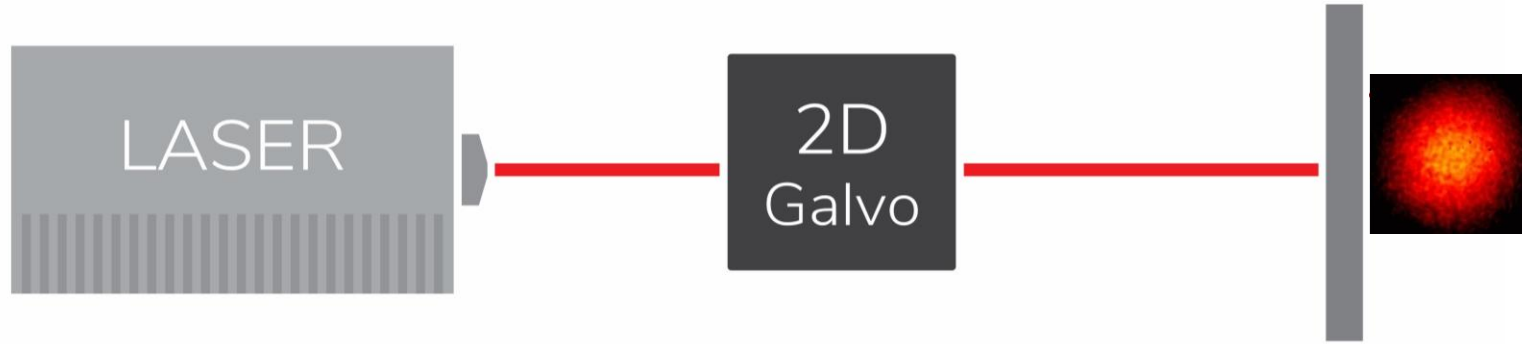


Using only scanning for laser beam delivery creates limitations in:

1. Throughput
2. Efficiency, especially for USP processing
3. Flexibility



Our solution: dynamically programmable multibeam laser processing



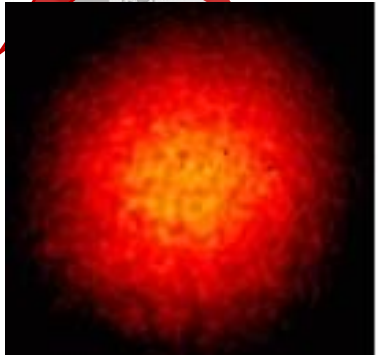
Standard laser processing
Sequential, like a pen on a sheet of paper



**Programmable
multibeam laser processing**
Dynamically parallelized, like a digital mask approach

Faster
More efficient
More flexible

The programmable multibeam technology



VULQ1 programmable multibeam technology
shapes light from the laser beam
on-demand and in real time
to maximize process performance at each step

VULQ1 generates up to hundreds laser beamlets on-demand, from one single laser beam.

The beamlets characteristics are individually and dynamically controlled by software - in position, profile and energy - to create the “*multibeam pattern*” fitted to the process needs.

The many beamlets composing the “*multibeam pattern*” are applied simultaneously to the material, scaling up throughput with no compromise on quality.

Multifold process throughput & efficiency increase
Spatial resolution < 50µm

Our purpose: Better laser solutions for a better manufacturing

Since 2011, QiOVA pioneers multibeam laser solutions to **enable cost-effective and ecofriendly late-stage personalization** of industrial goods

Surface treatment




Sustainable decoration,
functionalisation

Sectors :

Luxe, beverages,
cosmetics, automotive

Internal product traceability(B2B)



Track&Trace,
anticounterfeiting

Sectors:

Medical, luxe, electronics,
beverages

External product traceability (B2C)



Digital marketing, Digital
Product Passport

Sectors:

Durable consumer goods,
luxury goods, electronics

Industrial applications



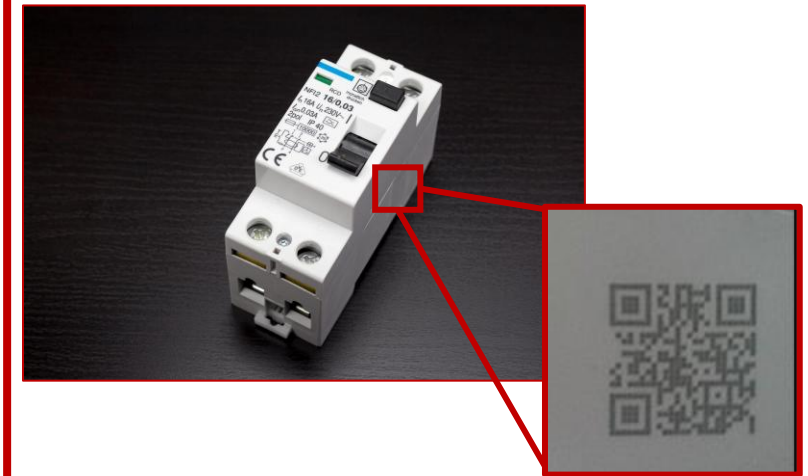
TISSEUR D'INNOVATION



Sustainable glass decoration
New design possibilities,
permanent, no addings
5x faster than standard laser



Serialization of medical devices
Permanent, seamless
integration in-line
72 000 parts / hour



Serialization of electrical goods
4x faster than current UV laser
marking
14 400 parts/hour

An unique offer of products and expertise to deliver superior throughput for industrial applications

Pre-sales service

Defining custom solution

- ✘ Feasibility studies
- ✘ Application development
- ✘ Pre-series

VULQ1 Multibeam OEM offer

Delivering higher performance

- ✘ Manufactured in our factory
- ✘ Standard and custom OEM systems
- ✘ Retrofit/integration in environment

After-sales service

Maximizing uptime

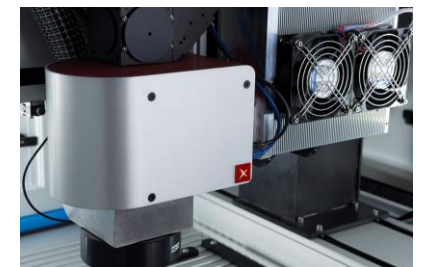
- ✘ Maintenance
- ✘ Warranty extension
- ✘ Contracted services



VULQ1-M
Optical module



VULQ1-S
Laser marking systems



Custom Laser
marking systems

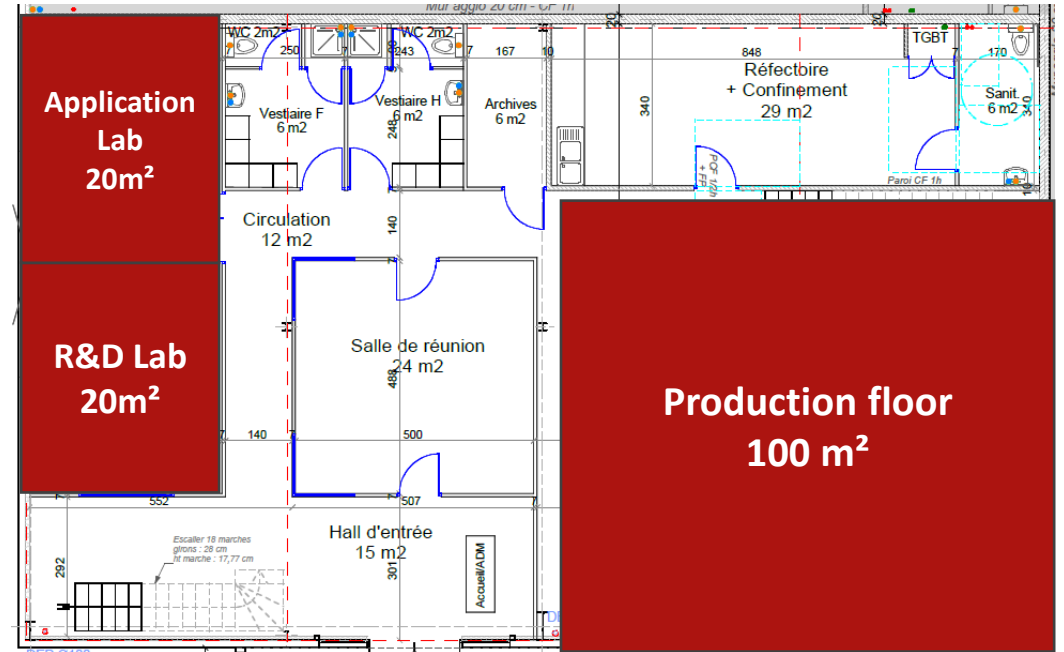


QiOVA – Our factory



- **Factory located in the region of Saint-Etienne**
- Brand new industrial activity park
- 5min from highway, 1h from Lyon airport

- **Laser R&D laboratory**
 - Lasers: NIR & visible, up to 30mJ, 25W, nanosecond to femtosecond
 - Equipment: 3D printer, characterization
- **Application laboratory**
 - VULQ1 STAMP marking systems
- **Production**
 - 50-100 VULQ1 modules / year
 - 20 VULQ1 systems / year





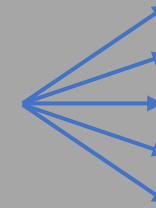
IP Qiova – A growing international patent portfolio

Patent family n°1 FLASH marking

[FR3023206B1](#) (process + system)
[FR3023207B1](#) (principle of use)



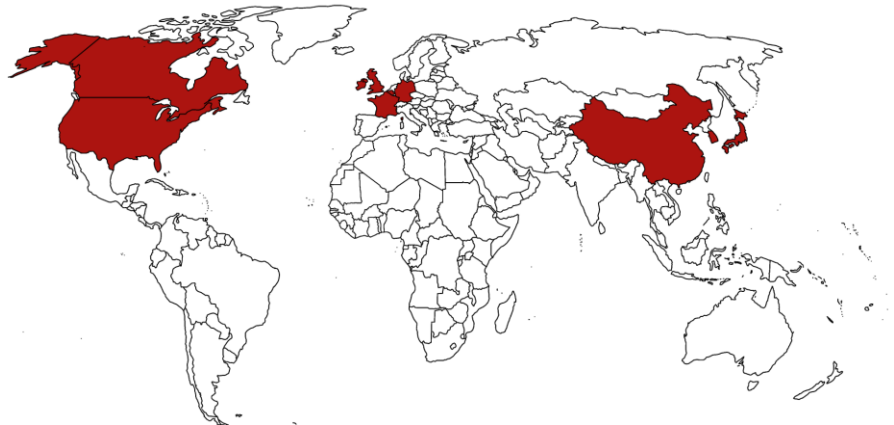
[WO2016001335A1](#)
(PCT extension)



[EP3164828B1](#) (GB, FR, DE, BE)
[CA2953439C](#)
[CN106573336B](#)
[JP6720156B2](#)
[KR101904680B1](#)
[US10350705B2](#)

Patent family n°2 High-speed printing

France - FR [3121060](#)
International Extension – [WO/2022/208020](#)



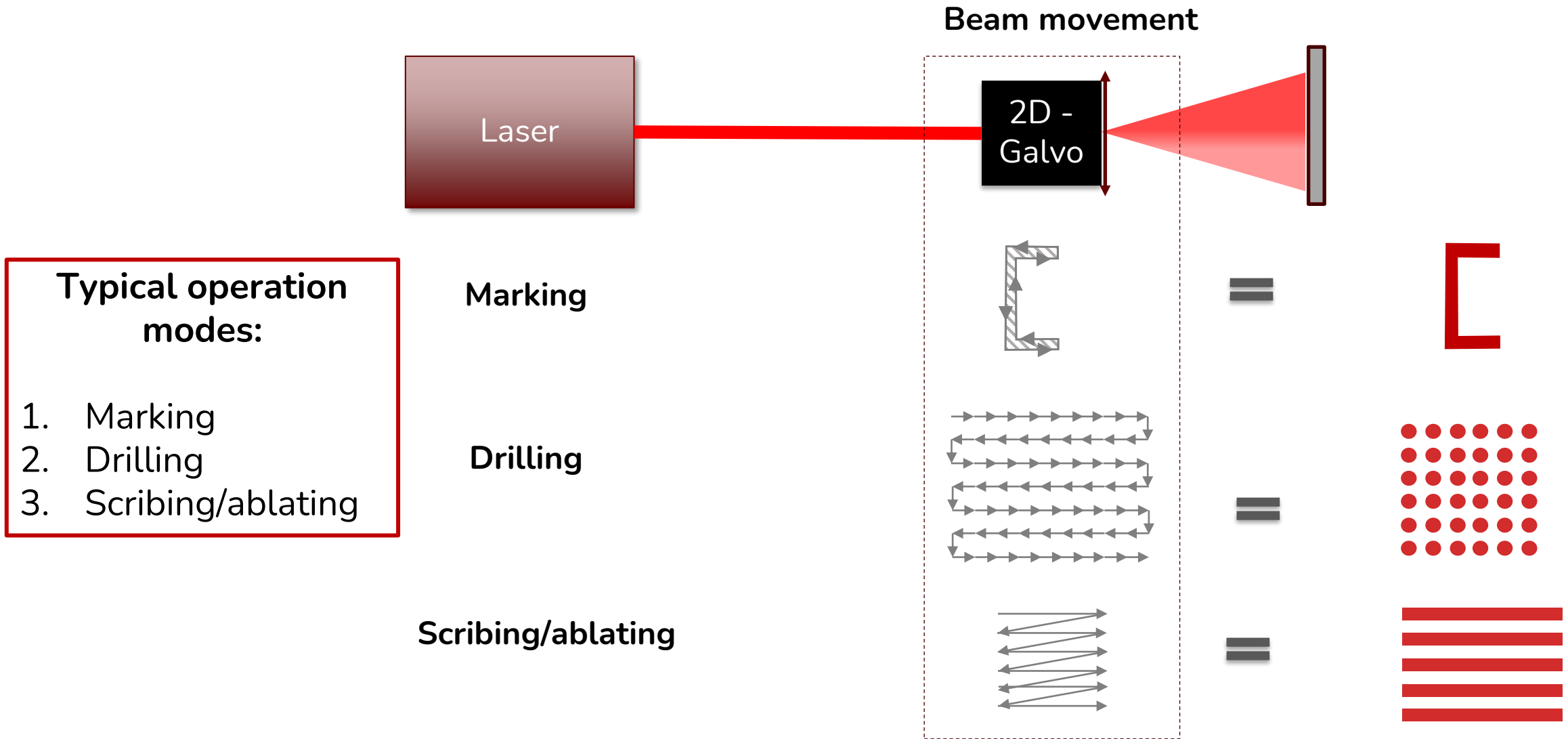
Additional IP pending for the micromachining sector



From standard laser processing to multibeam laser processing



Standard laser processing



- Typical operation modes:**
1. Marking
 2. Drilling
 3. Scribing/ablating

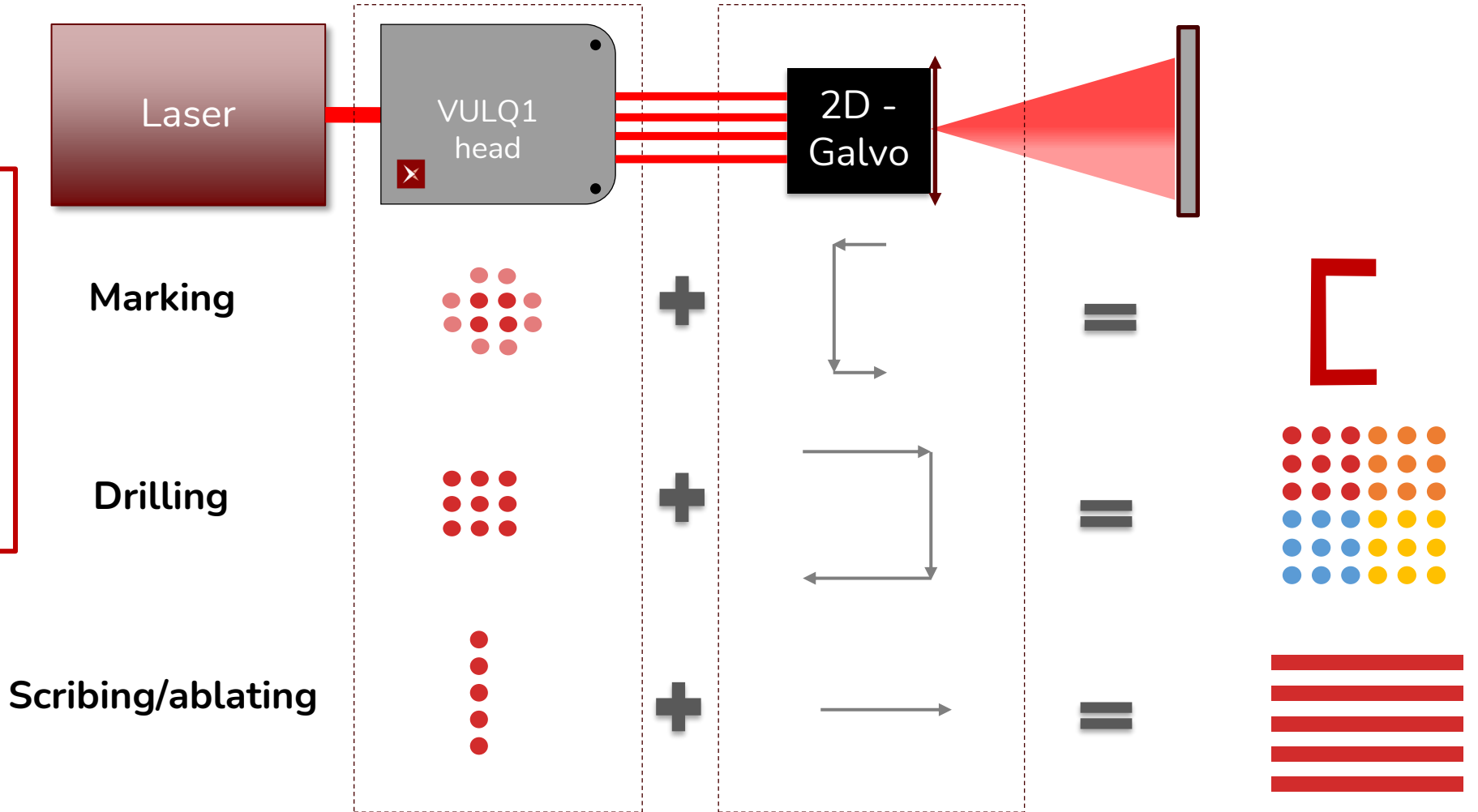
Marking

Drilling

Scribing/ablating

Multibeam laser processing eliminates useless movements

Beam shaping + Beam movement = More throughput
More capabilities

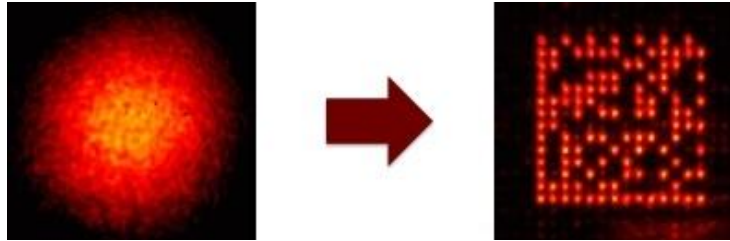


Less beam movement = More throughput

VULQ1 unique marking methods = laser stamping

PATENT#1
FULL-STAMP marking method

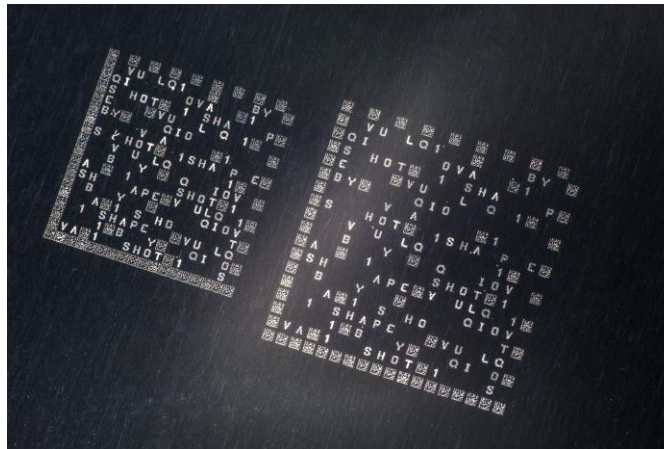
ONE LASER PULSE = ONE MARKING



[Link to youtube video](#)

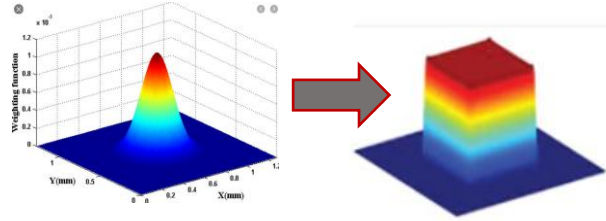
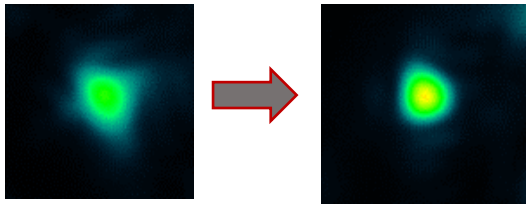
PATENT#2
PIXEL-STAMP marking method

HIGH SPEED LASER STAMPING



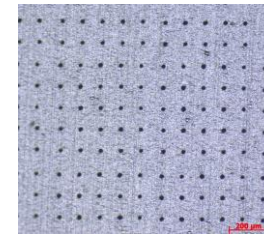
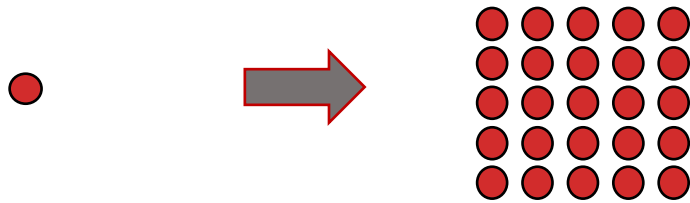
Unleash the full potential of laser processing with VULQ1

1. Optimal and homogeneous processing quality with active beam profile control



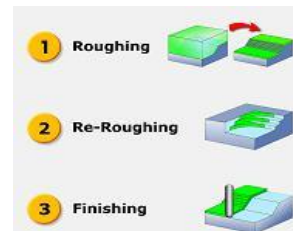
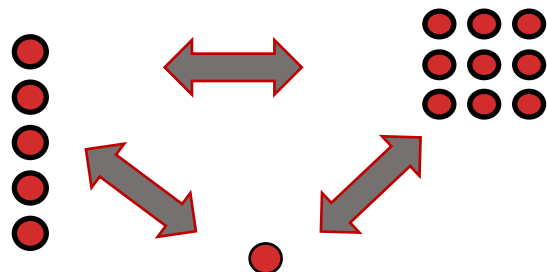
*Process optimization
Output standardisation
Remote maintenance*

2. Multiply throughput with parallelization



*12500 holes/s in SS with 12,5W
20µm diameter holes
92% roundness*

3. Switch between 'multibeam patterns' to optimize efficiency



*Same processing strategy as
on a CNC machine
Switching time < 100ms*

Programmable multibeam processing is operated like standard laser processing

Standard *Laser marking sequence*

1. Configure scanner software
 - a) Load laser settings:
 - Power
 - Repetition rate
 - b) Load scanner settings
 - Trajectories
 - Scanning speed
2. Start laser marking job

Multibeam *Laser marking sequence*

1. **Configure BeamForge API**
 - a) **Choose pre-loaded laser beam shape**
 - b) **Define custom laser beam shape**
2. Configure scanner software
 - a) Load laser settings:
 - Power
 - Repetition rate
 - b) Load scanner settings
 - Trajectories
 - Scanning speed
3. Start multibeam laser marking job



- Same method to define laser marking jobs, also similar HMI
- Gaussian laser physics is the same in multibeam processing: no change defining focusing lens, spot sizes, etc..



VULQ1 offer

VULQ1™ Product Offer: From optical module to stand-alone laser marking system



VULQ1-S Systems FLASH series

Model NS NIR

Model NS VIS

VULQ1-S Systems BEAMS series

Model NS NIR

Model NS VIS

Model FS NIR

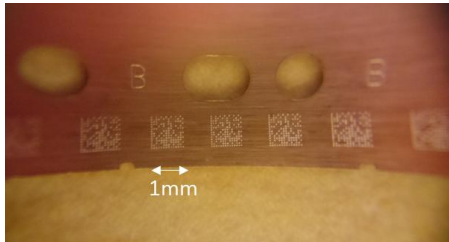
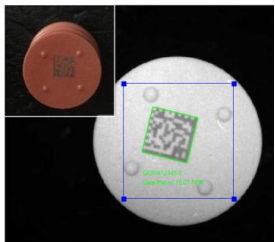
VULQ1-M Modules

BBD-P010

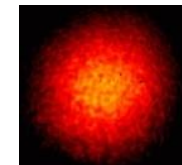
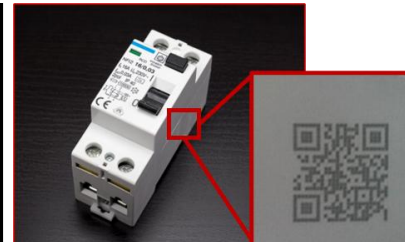
NIR-P050

VIS-P050

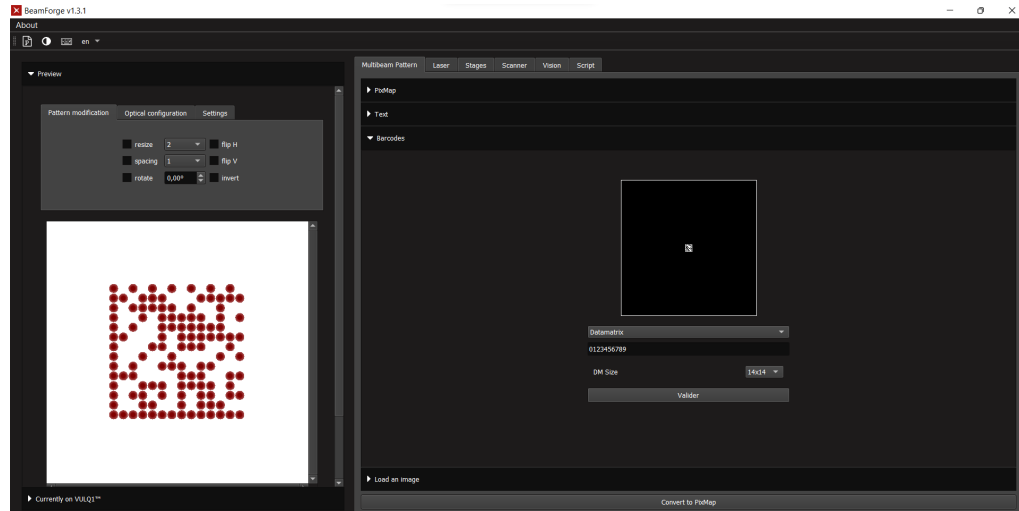
NIR-P100



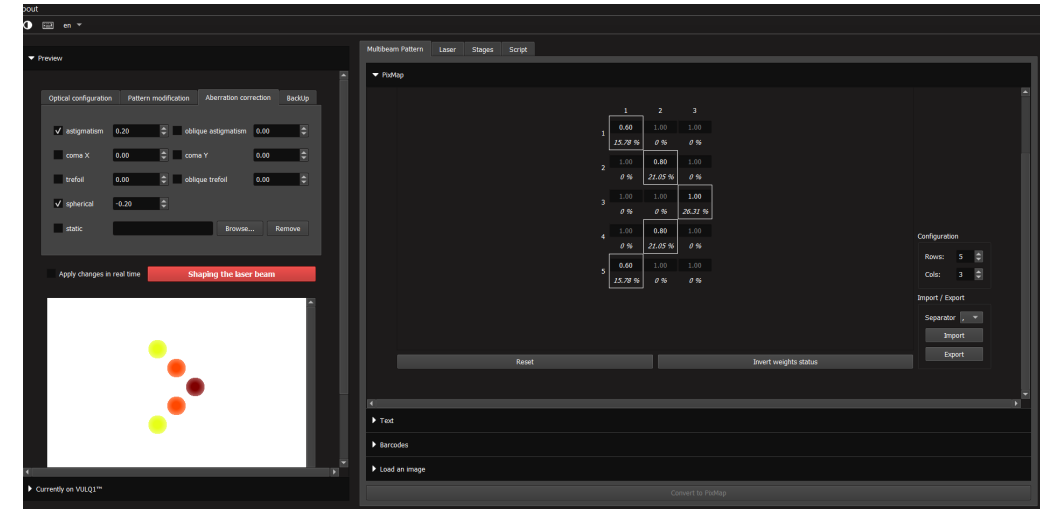
©: Pochet Ducourval



All powered by our proprietary software suite BeamForge

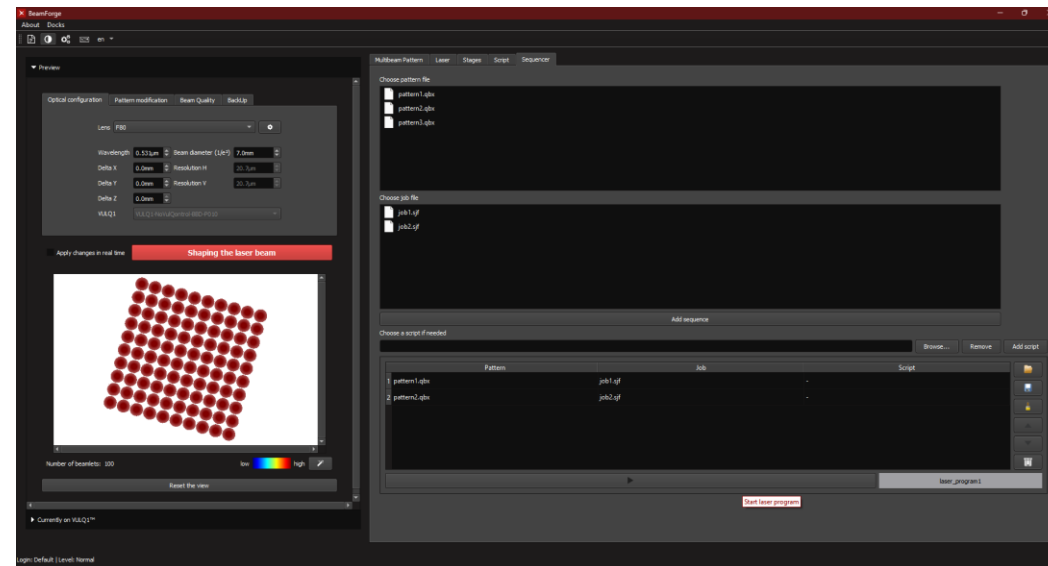


Generate 2D codes automatically from data



Create your own multibeam shapes interactively, save and reload on demand.

Drag-and-drop beam shapes, scanning jobs and scripts to create custom marking sequences





VULQ1-M Optical modules



VULQ1-M multibeam laser module - Components

1. VULQhead = VULQ1-M optical head

- Wavelength range: NIR or Visible
- Up to 30mJ energy
- Up to 100W power
- Down to fs pulse duration range



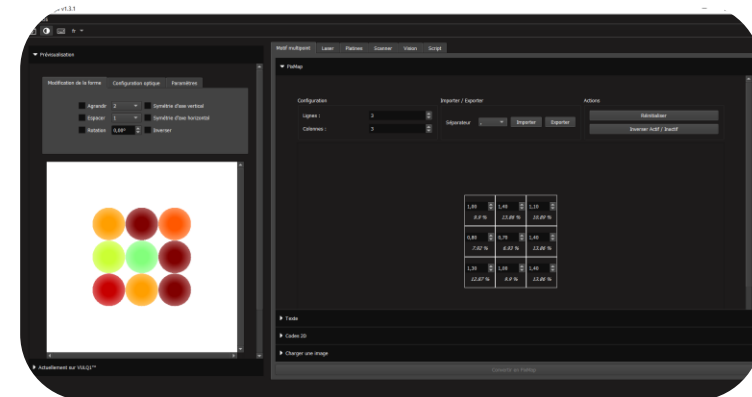
2. VULQontrol = VULQ1-M controller

- 2U rack 19" format
- 5m cable length between head and controller



3. BeamForge software

- Main software with interactive graphic tools
- Embeddable API version for integration

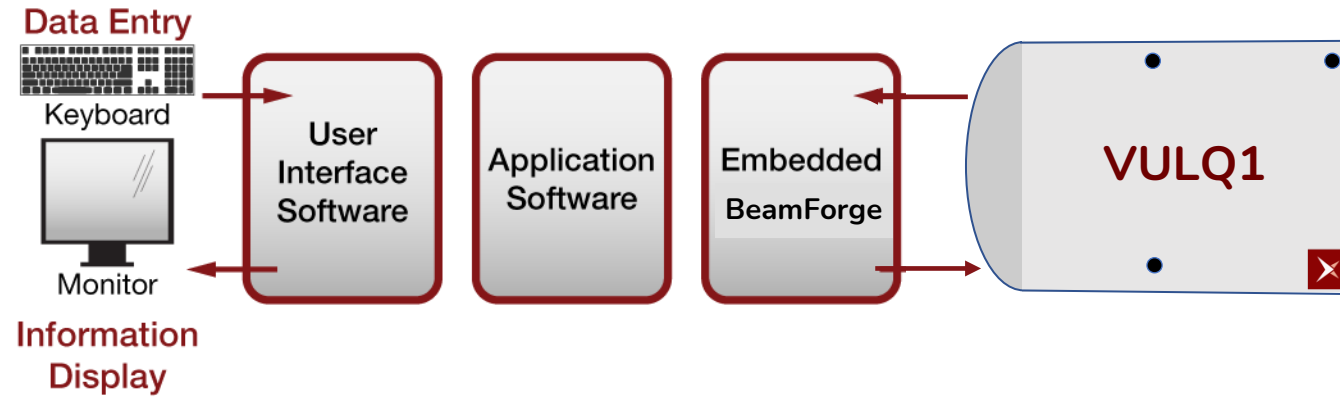


VULQ1-M Module standard offering

VULQ1-M product line	Scientific applications	Industrial applications		
		Marking		Micromachining
Model	NS-BBD-P010	NS-VIS-P050	NS-NIR-P050	FS-NIR-P100
Wavelength range	500-1100nm	500-550nm	1000-1100nm	1000-1100nm
Maximum power	10W	50W	50W	100W
Pulse duration	>1ns	>1ns	>1ns	>250fs
Maximum energy	10mJ	30mJ	30mJ	0,6mJ
Beam diameter input	5-7.5mm	5-7.5mm	5-7.5mm	6-10mm
Optical transmission	70%	90%	90%	90%
Switching time	60ms	65ms	115ms	100ms
Serialization rate	-	20Hz	10Hz	-
Minimum beamlet diameter (f80)	10µm	10µm	20µm	15µm
Minimum distance between beamlets (f80)	20µm	20µm	40µm	30µm
Maximum multibeam pattern dimension (f160)	5,6mm	2,8mm	5,6mm	5,6mm

Increasing maximum power to 200W in 2025!

BeamForge API delivers functions within *your* software environment



1. BeamForge software controls the **generation and display of Laser Light Tool**
2. BeamForge control software is **delivered as an API**
 - Seamless integration in HMI and customer experience
 - Minimal custom software development for integration

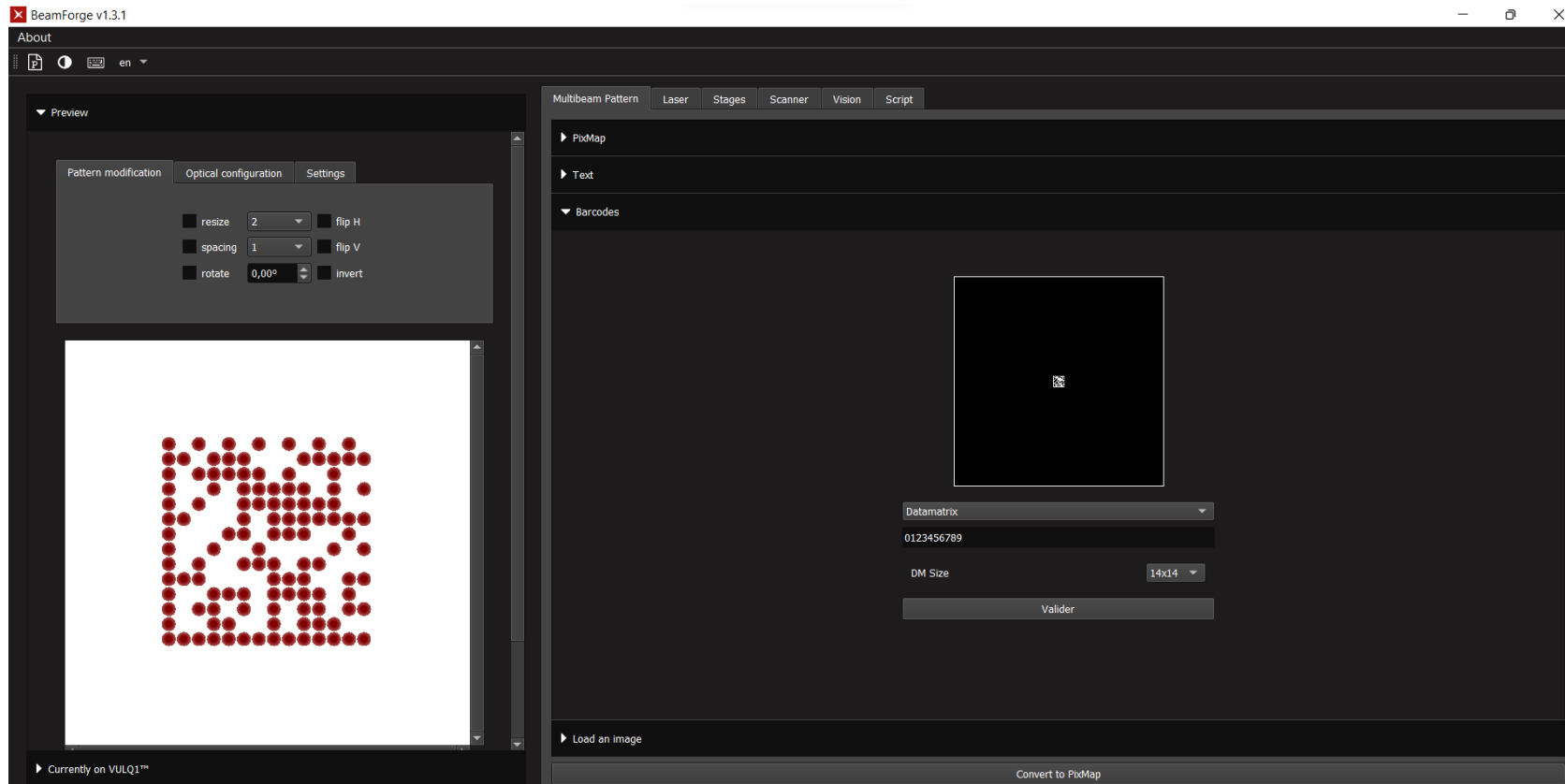




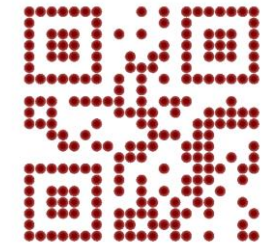
BeamForge Software



Built-in automated *multibeam patterns* generators



VULQ1-多点

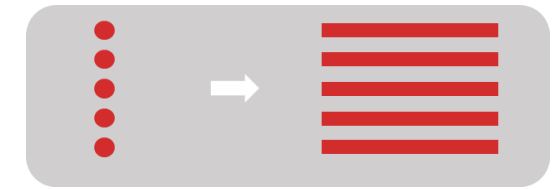
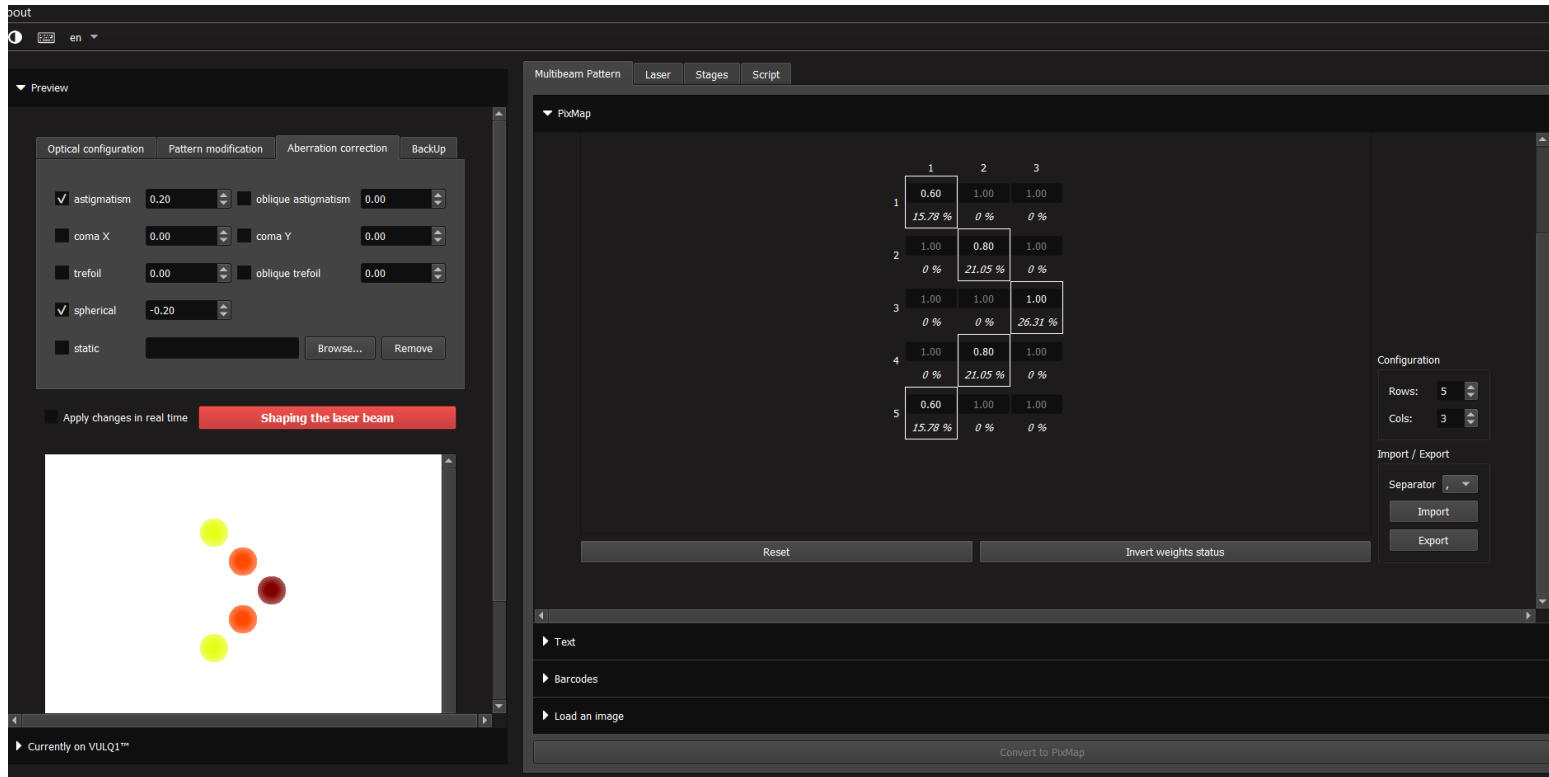


BeamForge automatically creates the Laser Light Tool from input data, in the targeted format

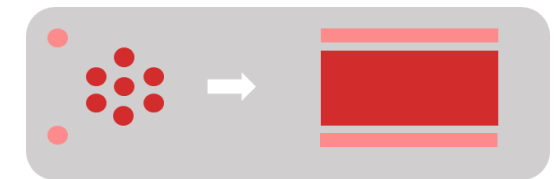
Input: alphanumeric or picture

Output format: Datamatrix, QR code, Dotcode, formatted text or picture

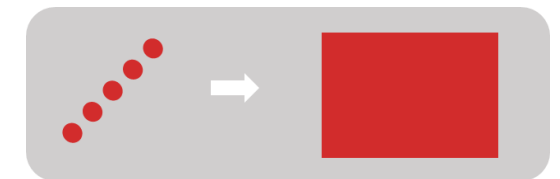
BeamForge software / MULTIBEAM marking method



Parallel Processing



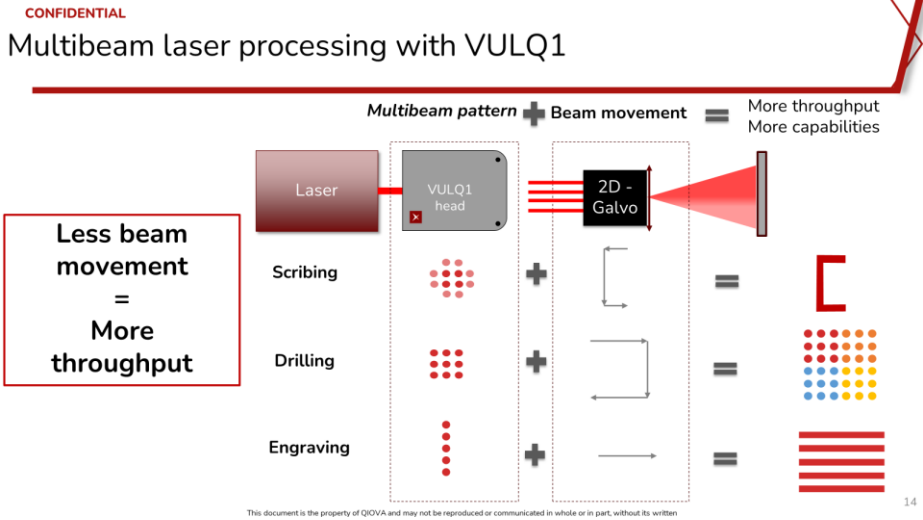
1 pass, several process steps



Linebeam-like processing

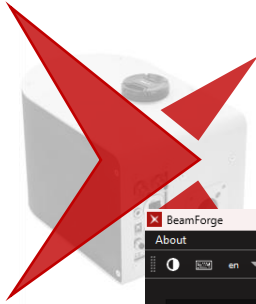
User can directly draw its Laser Light Tool from BeamForge PIXMAP interactive design tool
Here, a Datamatrix module with a pre-compensated 11° orientation to operate with a scanner.

A 3-steps process to create custom *Multibeam patterns*

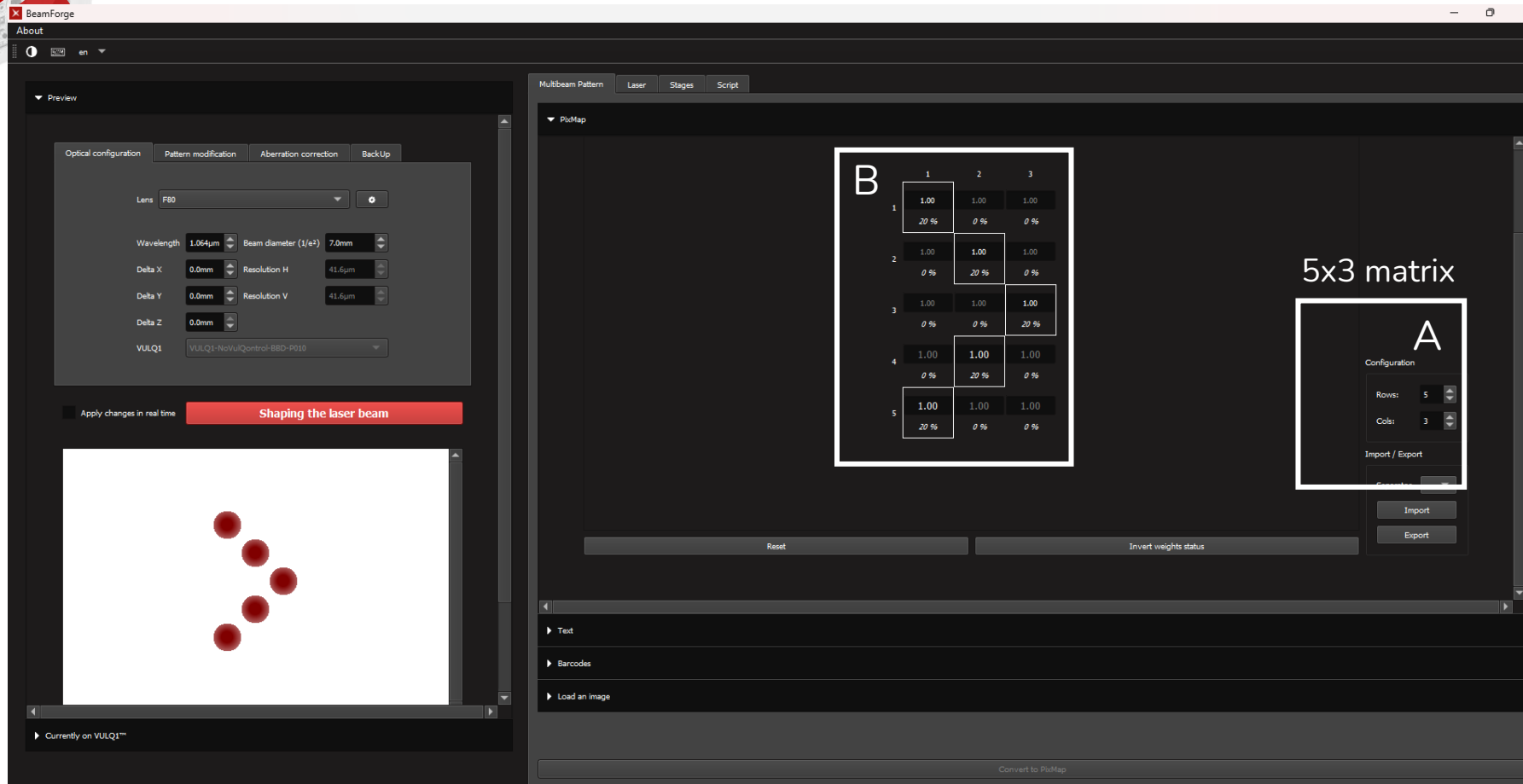


***Multibeam patterns* allow to use a maximum of available laser power in every context, therefore ensuring optimal throughput and efficiency.**

Step	Action	BeamForge function	
1	Define	PixMap	Sketch the beam pattern in a few clicks
2	Set	Pattern modification	Modify beam pattern globally: rotate, expand, ..
3	Configure	PixMap, DeltaZ, Beam Quality Control	Fine tune beam pattern energy distribution, dimensions, quality to finalize 'laser brush'



Step 1 - Define with PixMap



BeamForge PixMap
Interactive design tool

- ✦ Define the virtual 2D matrix supporting the pattern (A)
- ✦ Click on the cells you want to activate (B)



Step 2 – Set to the optical setup

The screenshot shows the BeamForge software interface. On the left, the 'Pattern modification' tab is active, showing settings for 'rotate' set to 13.00°. A white box labeled 'C' highlights these settings. Below this is a 'Shaping the laser beam' button and a preview window showing a 5x3 grid of red spots with a dashed red line and arrow indicating a rotation. A white arrow labeled 'D' points to the 'Preview' section. On the right, the 'PiMap' grid is displayed, showing a 5x3 grid of spots with weights of 1.00 and 0.00. A 'Configuration' panel on the right shows 'Rows: 5' and 'Cols: 3'. At the bottom, there are 'Reset' and 'Invert weights status' buttons, and a 'Convert to PiMap' button.

- ✦ Globally modify pattern with Pattern modification functions (C)
 - ✦ Here: 13° pattern rotation to pre-compensate rotation in scanning head
- ✦ Eliminate central spot with “DeltaZ” function (D)



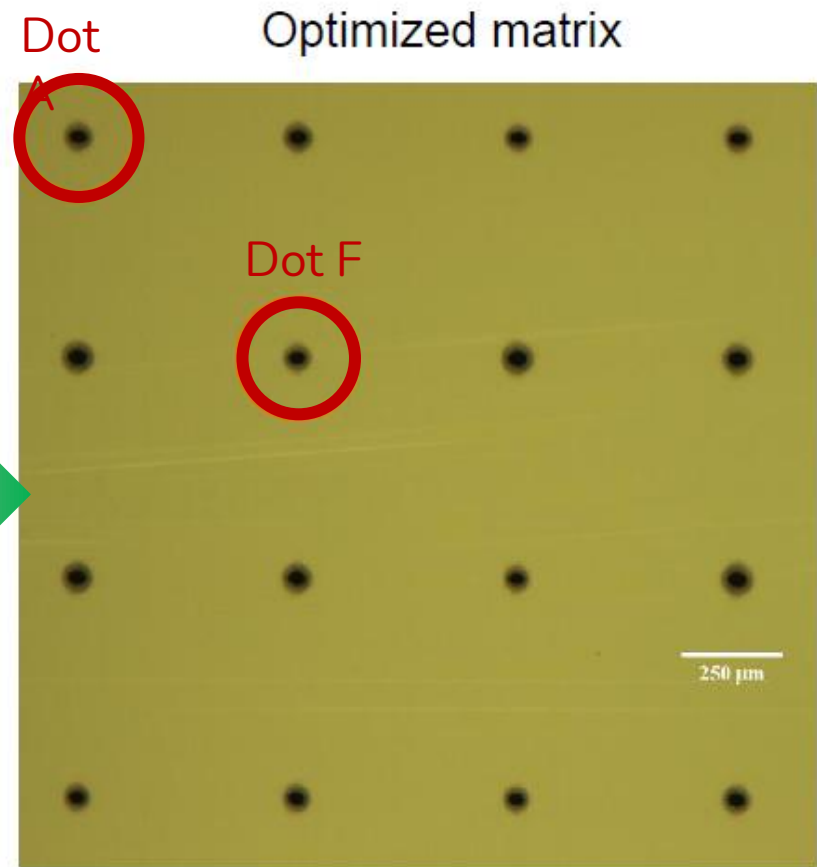
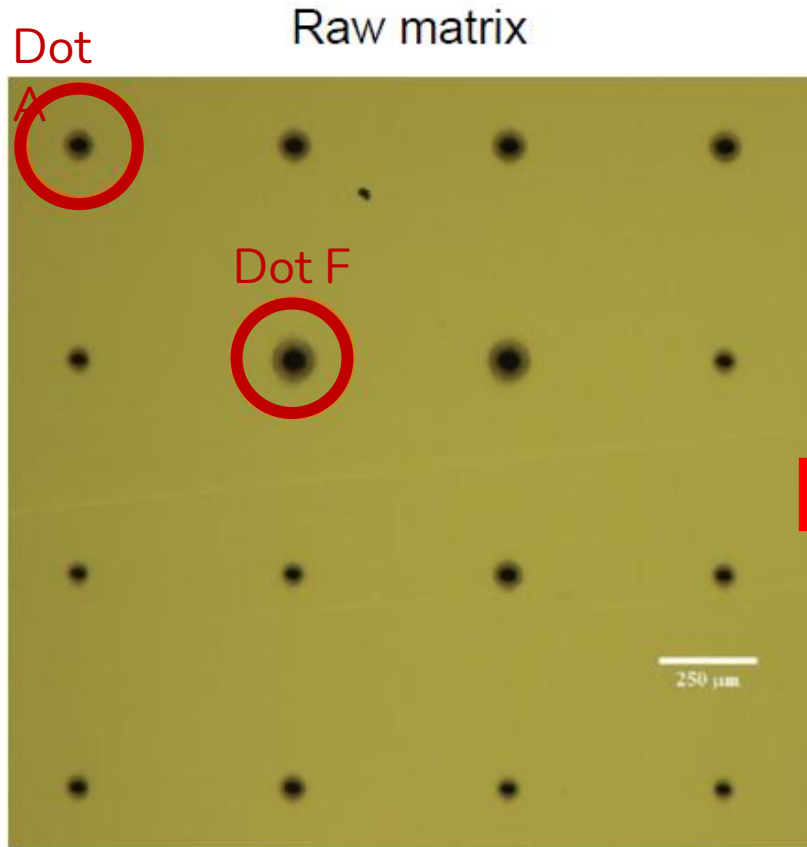
Step 3 – Configure to application

The screenshot displays a software interface for configuring a laser beam. The interface is divided into several panels:

- Preview Panel (Left):** Contains a "Beam Quality Control" menu (labeled F) with settings for astigmatism, coma, trefoil, and spherical aberrations. Below this is a "Shaping the laser beam" button and a preview window showing a multi-spot beam profile.
- PixMap Panel (Right):** Shows a 5x3 grid of beamlets (labeled E) with individual energy and weight controls. The grid is labeled with "1" through "5" for rows and "1" through "3" for columns.
- Configuration Panel (Bottom Right):** Includes "Rows: 5" and "Cols: 3" settings, and "Import / Export" options.
- Bottom Panel:** Contains a "Convert to PixMap" button and a list of options: "Text", "Barcodes", and "Load an image".

- ✦ Tune beamlets energy with PixMap individual energy control (E)
- ✦ Optimize beam profile with “Beam Quality Control” menu (F)

Energy fine tuning is critical for micromachining



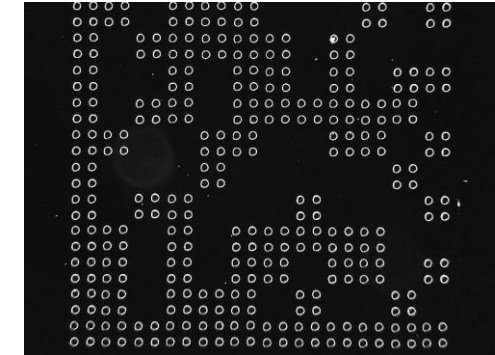
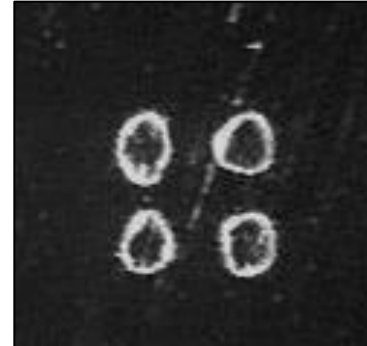
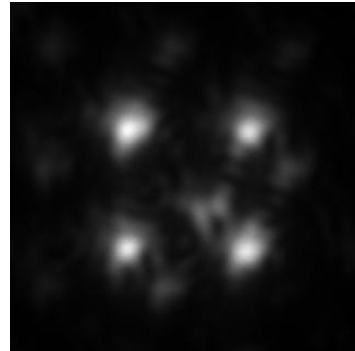
Optimization with VULQ1

	Diameter (μm)	Depth (μm)
Dot A raw	40,000	0,982
Dot F raw	50,120	2,107
Difference D (%)	25%	115%

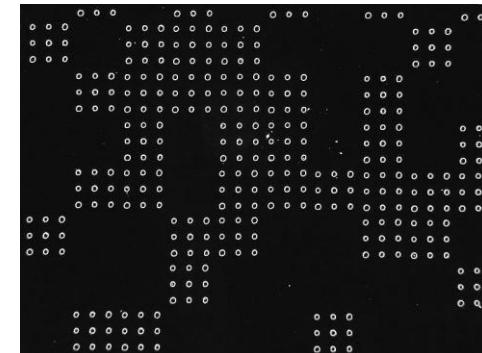
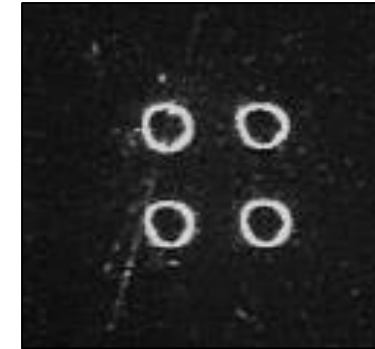
	Diameter (μm)	Depth (μm)
Dot A optimized	37,590	0,932
Dot F optimized	36,627	0,951
Difference D (%)	3%	2%

Beam Quality Control, a lever to improve global performance

WITHOUT
VULQ1



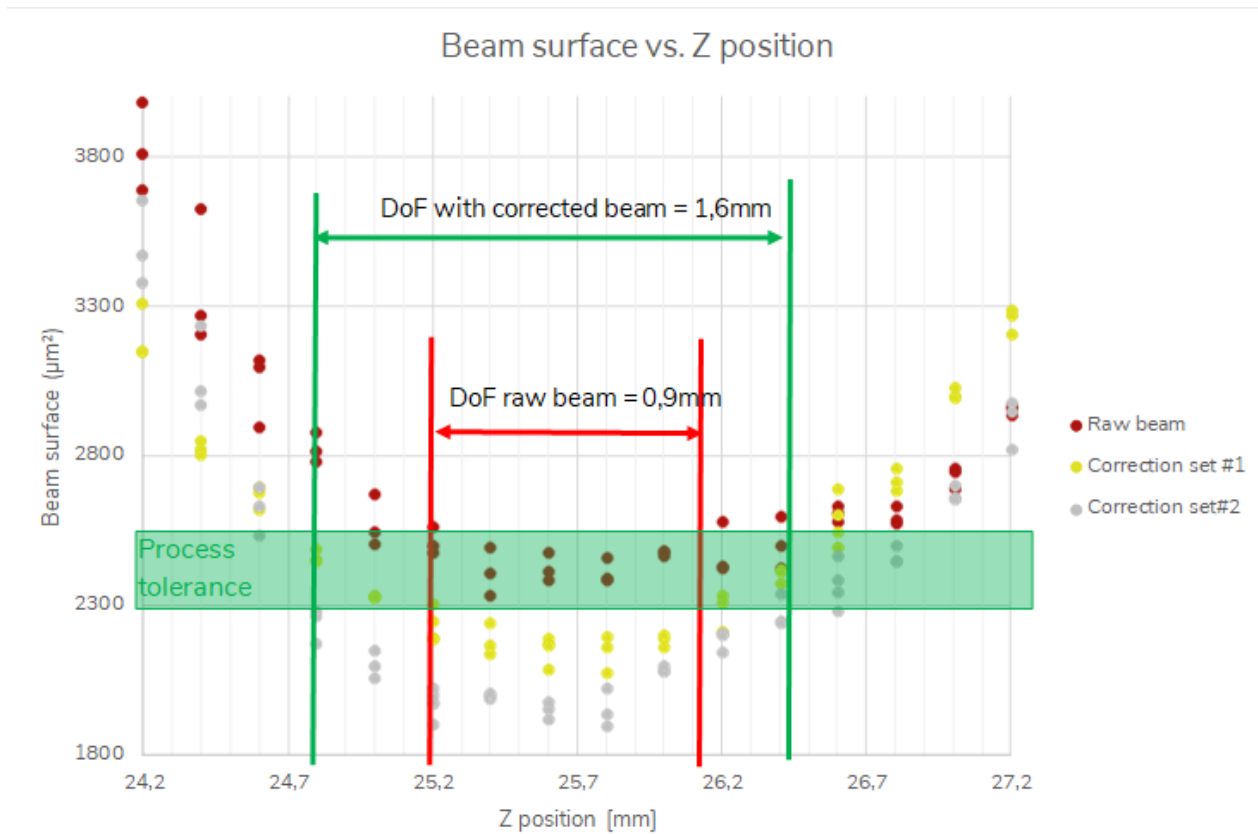
WITH VULQ1
BEAM
QUALITY
CONTROL



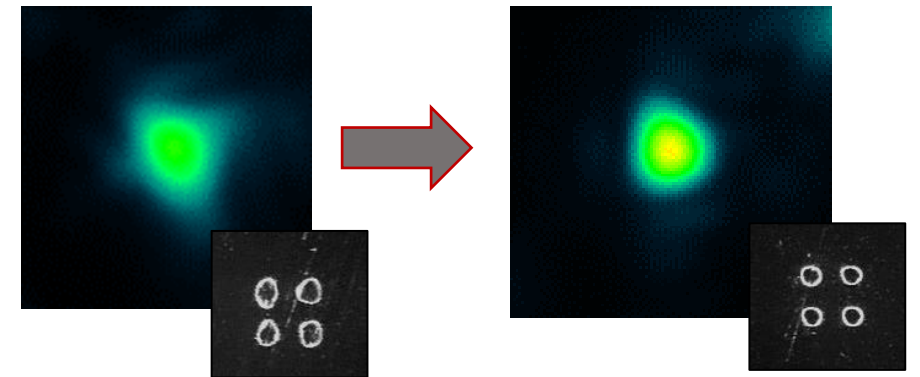
- **Improved process robustness:** larger depth of focus
- **Improved processing quality:** rounder beam, tighter focusing,
- **Standardisation of output performance** for large installations
- **Reduced downtime** with dynamic management of laser beam quality along lifetime

Beam Quality Control benefits process robustness

- For laser processing: depth of focus (DoF), typically ~mm
- Brings strong mechanical positioning constrains for industries



Currently available in VULQ1



Improving laser beam
quality increases process
DoF by 75%



Save and load your multibeam patterns on demand

The screenshot displays the QIOVA software interface for configuring multibeam patterns. The interface is divided into several sections:

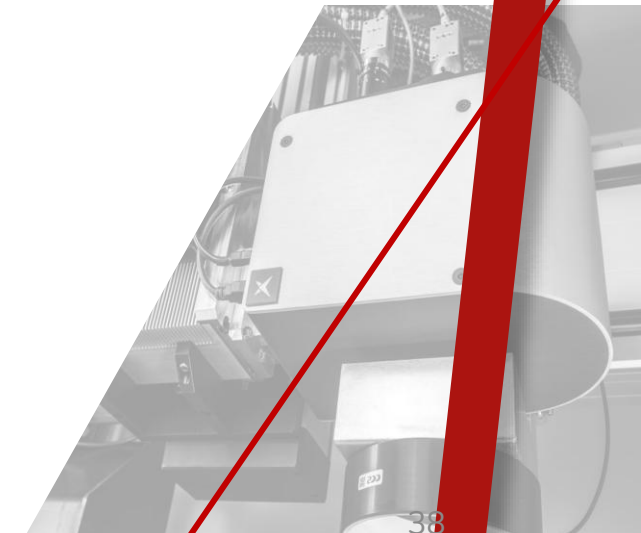
- Preview:** Contains tabs for 'Optical configuration', 'Pattern modification', 'Aberration correction', and 'BackUp'. It includes various sliders and checkboxes for parameters like astigmatism, coma, trefoil, and spherical. A 'Shaping the laser beam' button is visible.
- Multibeam Pattern:** Features a 'PixMap' section with a 5x3 grid of values. The values are:

	1	2	3
1	0.60 15.78 %	1.00 0 %	1.00 0 %
2	1.00 0 %	0.80 21.05 %	1.00 0 %
3	1.00 0 %	1.00 0 %	1.00 26.31 %
4	1.00 0 %	0.80 21.05 %	1.00 0 %
5	0.60 15.78 %	1.00 0 %	1.00 0 %
- Configuration:** Includes 'Rows: 5' and 'Cols: 3' settings.
- Import / Export:** Features a 'Separator' dropdown menu, 'Import', and 'Export' buttons. A red 'G' icon is present next to the separator menu.
- Buttons:** 'Reset' and 'Invert weights status' buttons are located below the PixMap table.
- Footer:** Includes a 'Convert to PixMap' button and a status bar showing 'Currently on VULQ1™'.

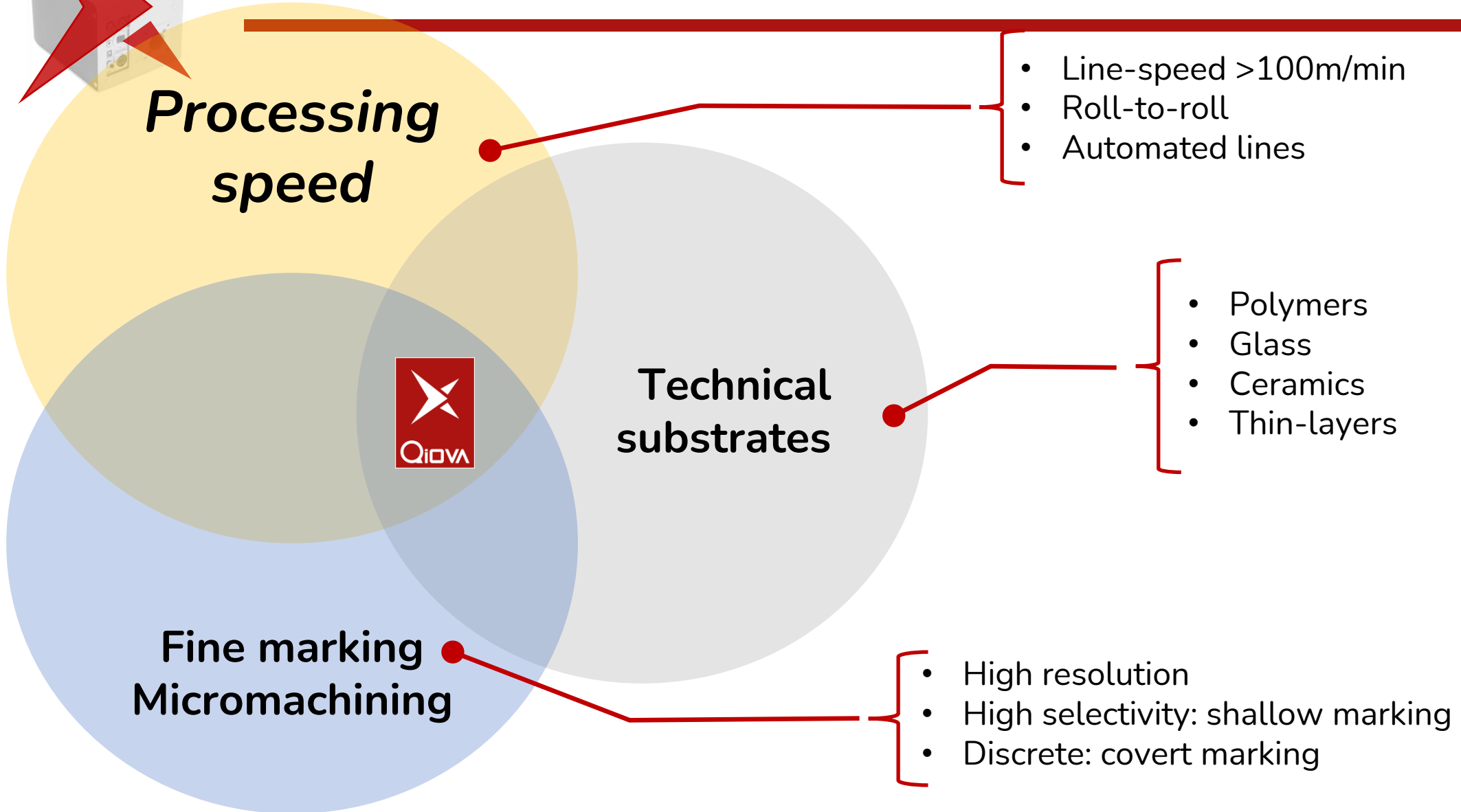
- ✦ The multibeam patterns are stored in .csv and recalled at wish (G)
- ✦ Changing one multibeam pattern to another takes 50-100ms



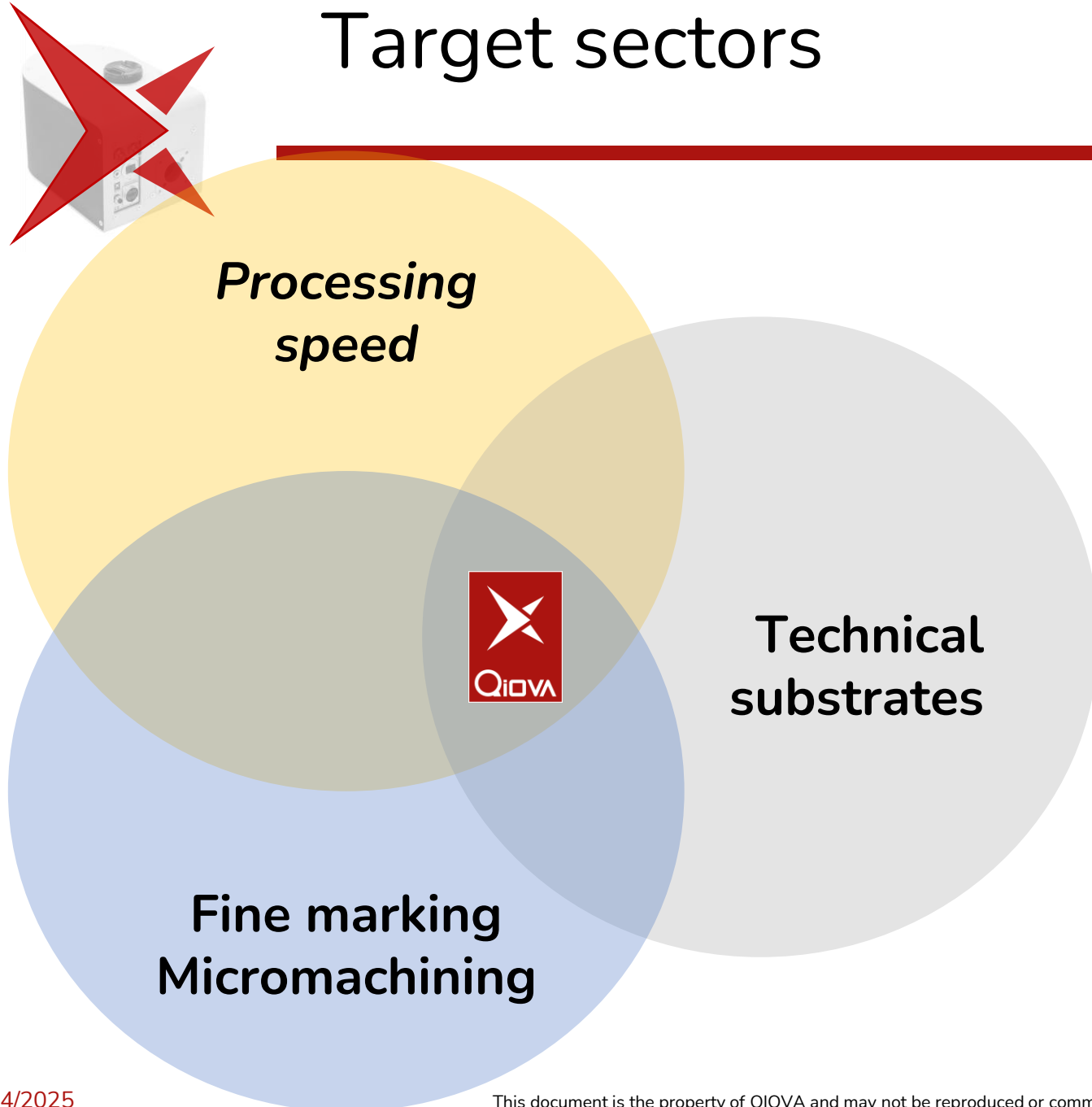
VULQ1 multibeam applications



Technology differentiation regions



Target sectors



Electrical products



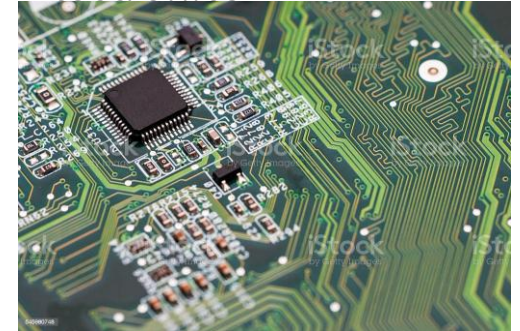
Medical devices



Luxe



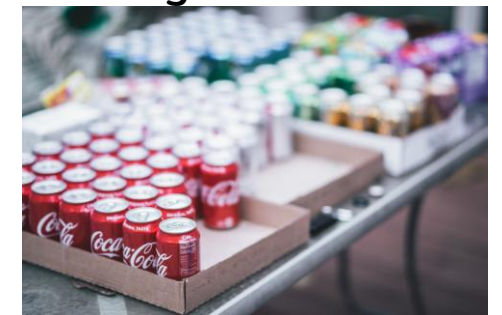
Electronics



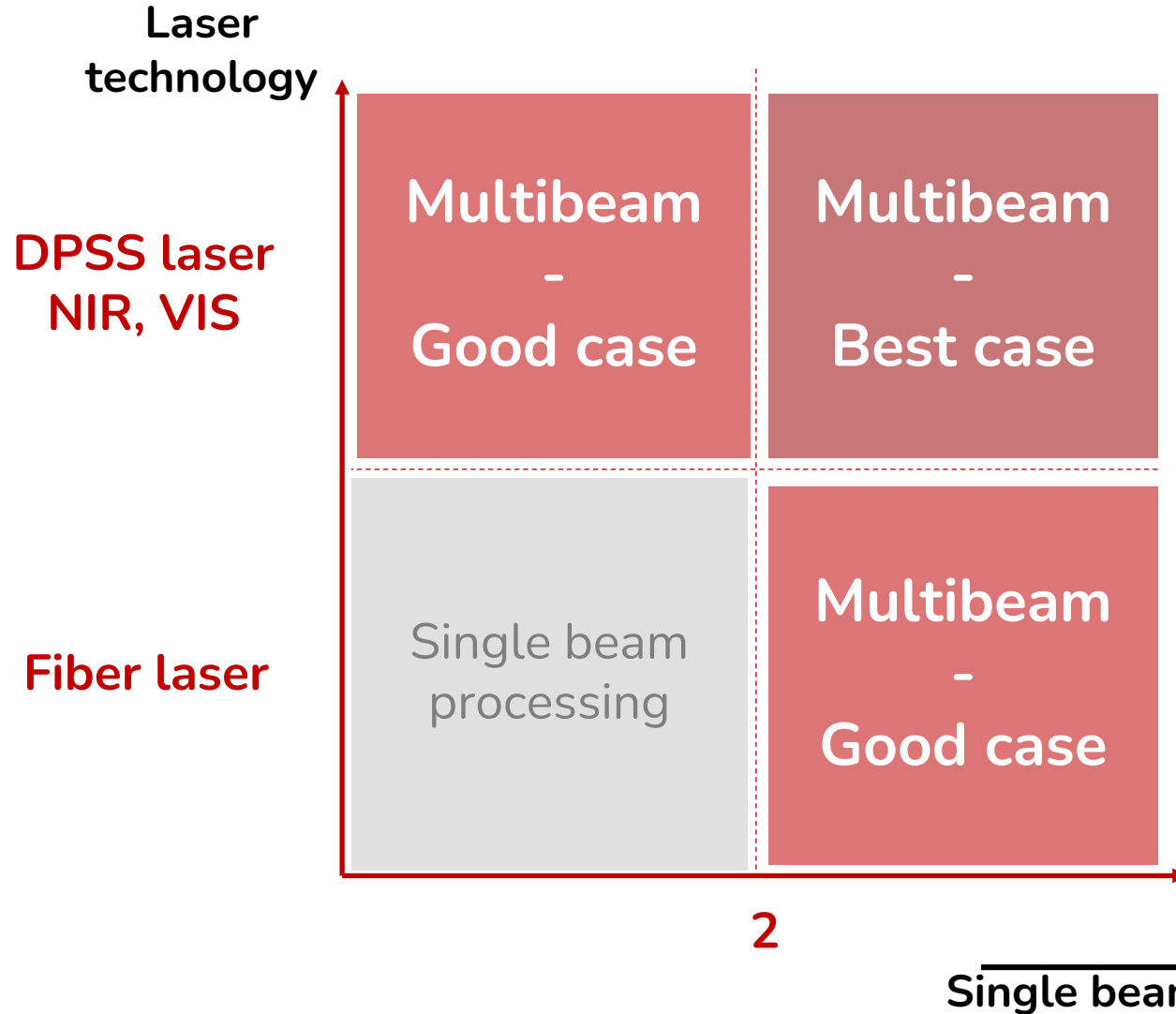
FMG packaging



Beverages



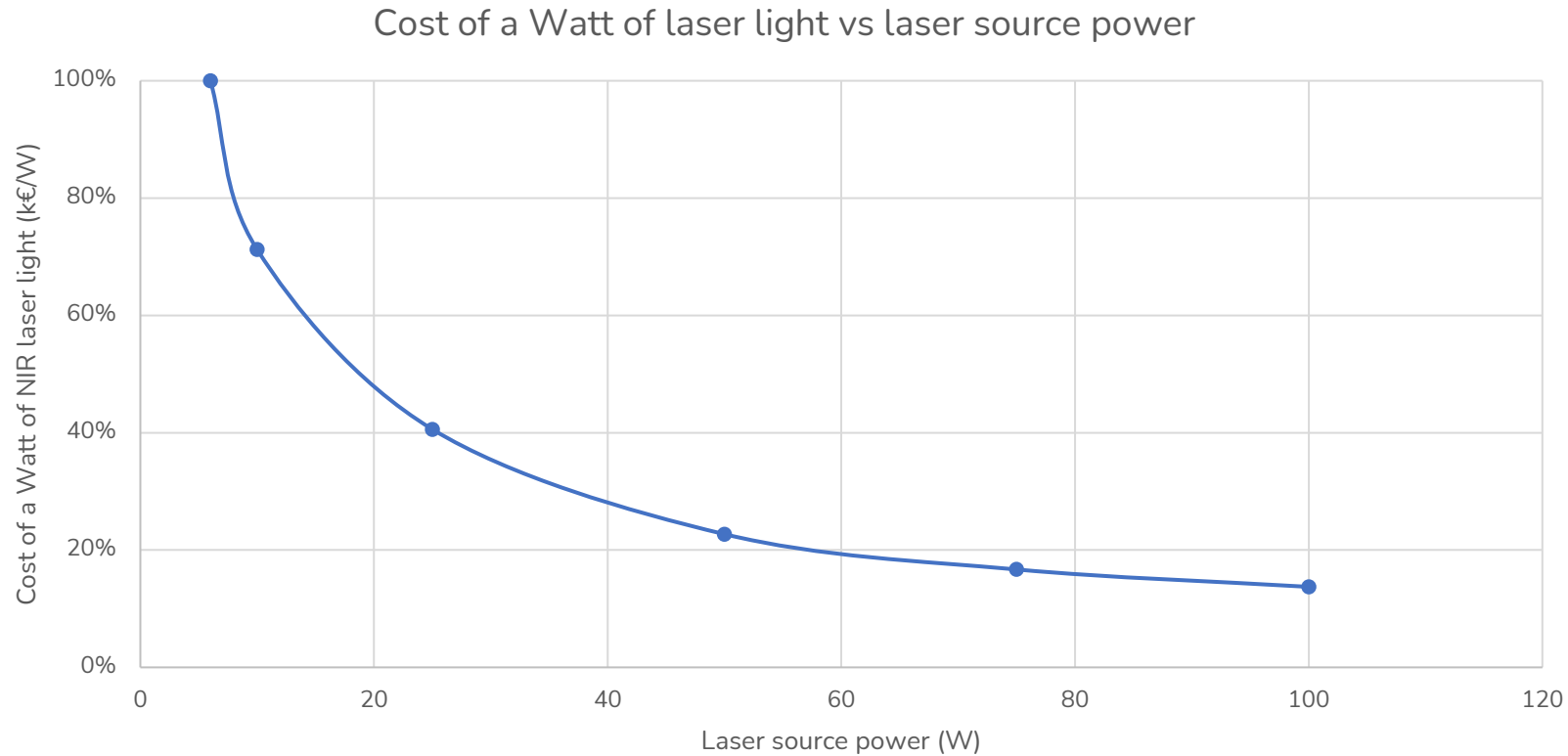
Wondering if multibeam processing could help?



Multibeam processing could be very beneficial to your application if:

1. Your laser is a DPSS operating in NIR or VIS
2. Single beam process point is < 50W (the lower, the better)

High power laser source brings reduction cost indeed...

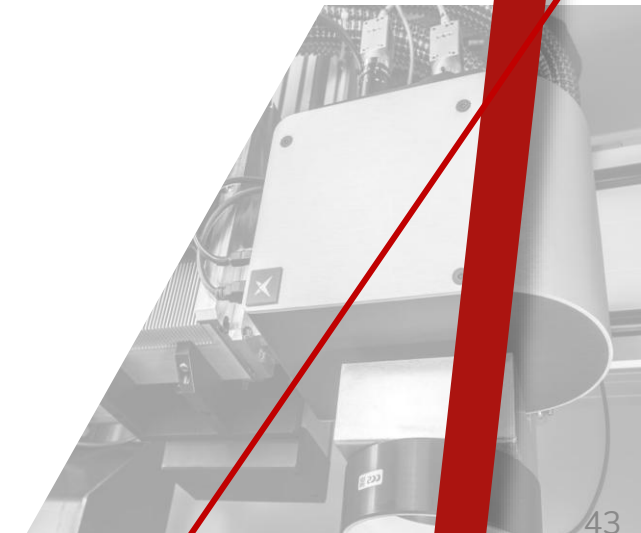


**€/W is 5x lower
with
a 100W laser**

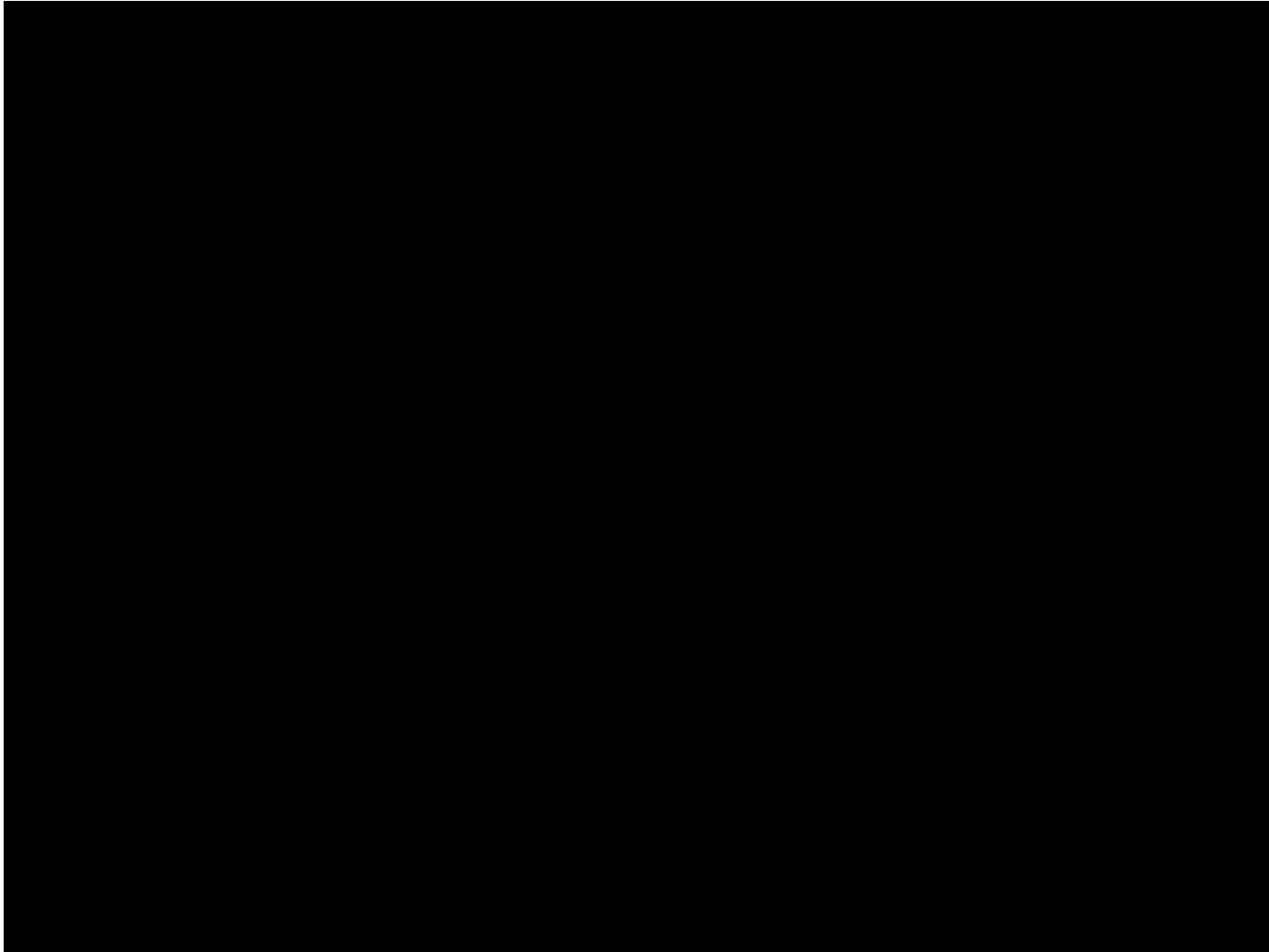
...but only if the process uses the full power available



Examples of **ACCELERATION** with VULQ1-M



Metal surface texturing with femtosecond laser



5 % additional CAPEX
investment
=
500% productivity

**Multibeam processing
is 5x faster**

[On Youtube:](https://www.youtube.com/watch?v=CuglV8akasY)

<https://www.youtube.com/watch?v=CuglV8akasY>

Decoating of thin metal layer with ns laser

- **Current laser solution**
 - Process point = 20W, limited by quality consideration
- **Multibeam processing**
 - 60W on the sample, same scanning method



*Selective ablation quality comparison
single beam vs multibeam*



Multibeam processing is 3x faster

Marking of additived PET bottles with ns laser



Multibeam processing is:

- 3x faster for alphanumeric
- x5 for drawings



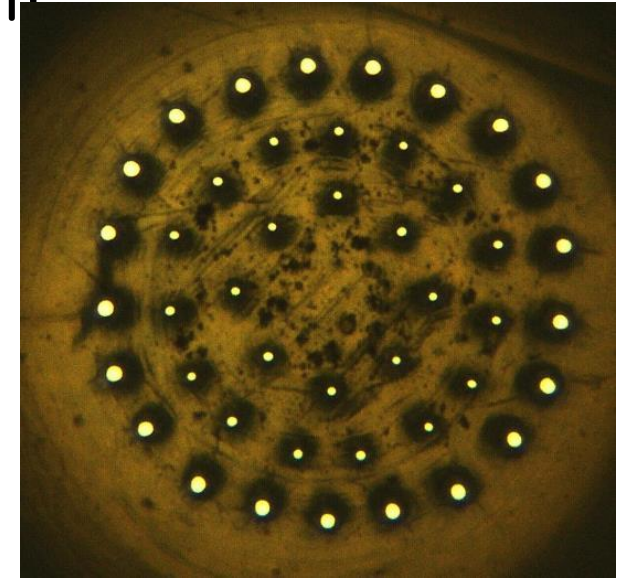
Multibeam processing

Industrial use case

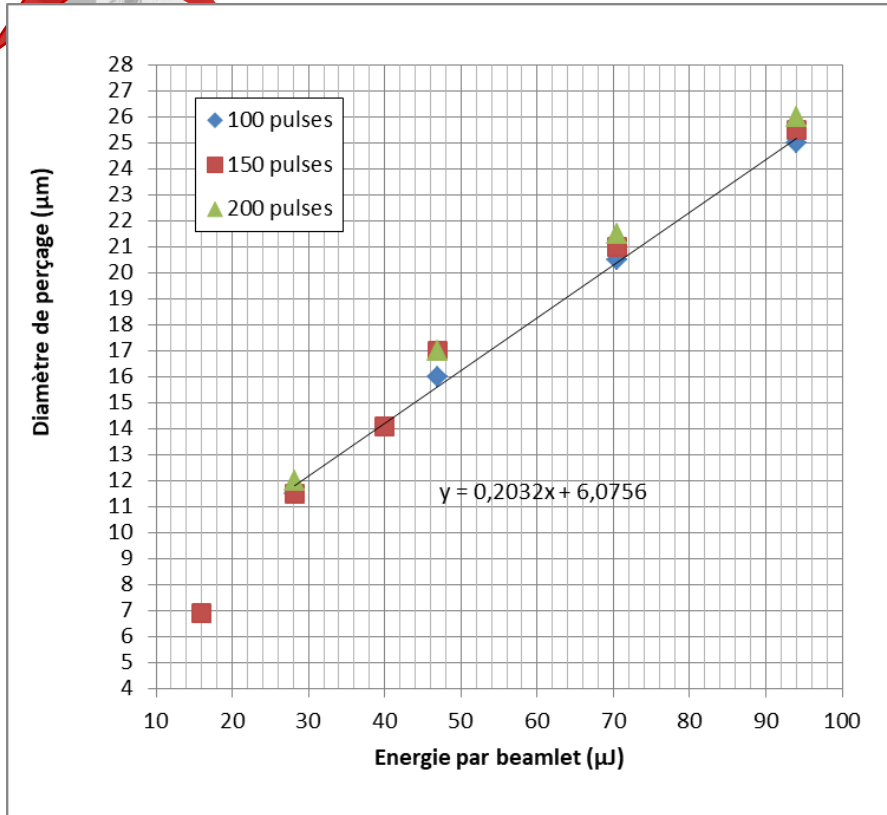


Example of industrial use case: micro-drilling

- Micro-drilling polymer material (thickness $\sim 250\mu\text{m}$)
 - Set of 44 micro-holes, with 2 sub-sets diameters:
 - D1 ($<10\mu\text{m}$)
 - D2 ($<20\mu\text{m}$)
 - Heat-sensitive material
 - Spatial distribution of holes is critical to function
 - Tolerance in relative position $<5\mu\text{m}$
 - Exit diameter of holes is critical to function, characterized by quality factor Δ :
 - $\Delta_{\{1,2\}} = \text{Max}(D_{\{1,2\}}) - \text{min}(D_{\{1,2\}}) < 2\mu\text{m}$
 - Cycle time $<1\text{s}$
 - The lower the better, projected production volume in millions/year



Laser matter interaction – single beam!



	Small holes diameter (D1)	Large holes diameter (D2)
Drilling process energy	14µJ	25µJ

Drilling rate	Quality factor for small holes (Δ ₁)	Quality factor for large holes (Δ ₂)
1 kHz	2,25µm	1,48µm
3 kHz	3,57µm	2,24µm

Δ (3kHz) / Δ (1kHz)	59%	51%
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- Study performed with a single beam, results translate into multibeam



- Robust 1st order correlation between energy and exit diameter : beam energy ↔ hole diameter



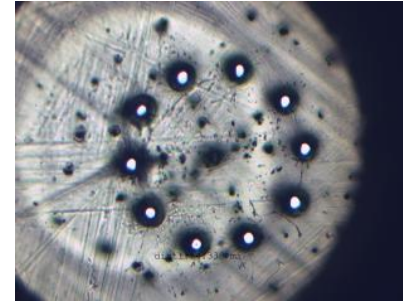
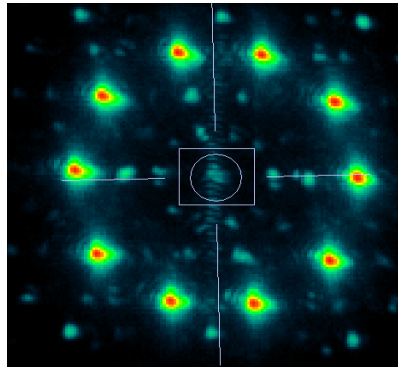
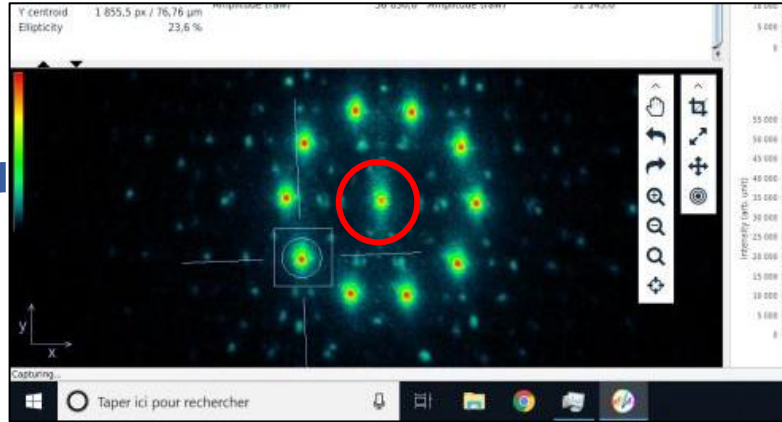
- The higher the repetition rate, the larger the quality factor Δ (thermal sensitivity!)



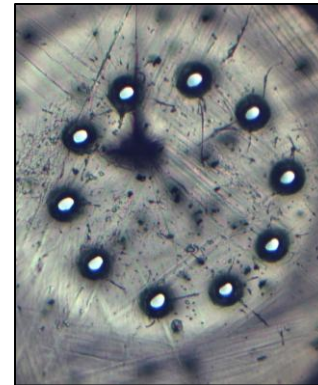
Creating the right 'laser brush' set: initial step

Central spot management Function

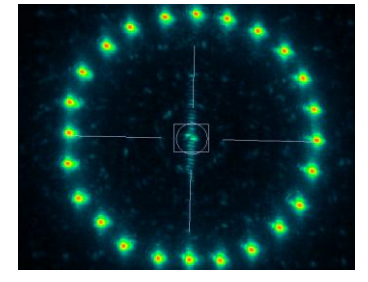
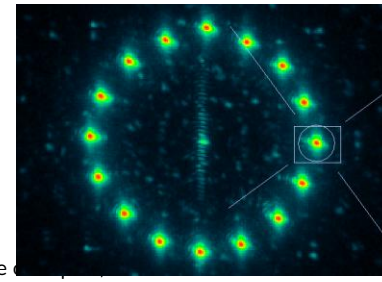
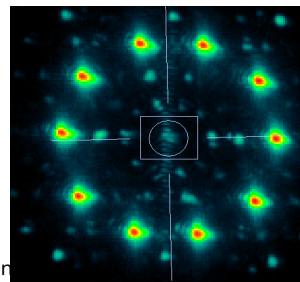
95% reduction



250fs, 1kHz
50µJ/beam
100 pulses/site



250fs, 1kHz
50µJ/beam
150 pulses/site

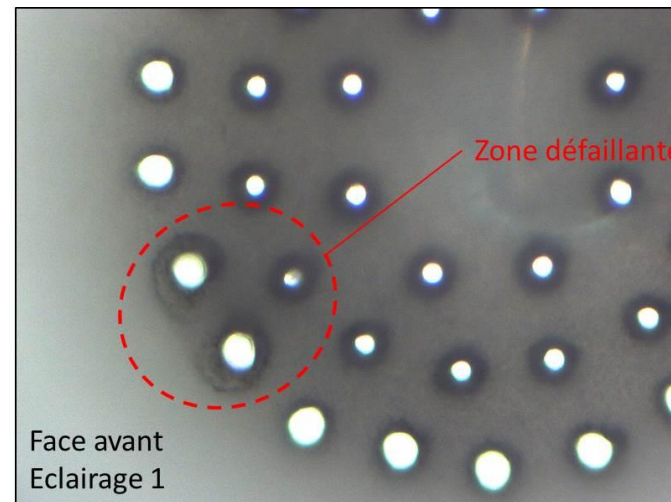
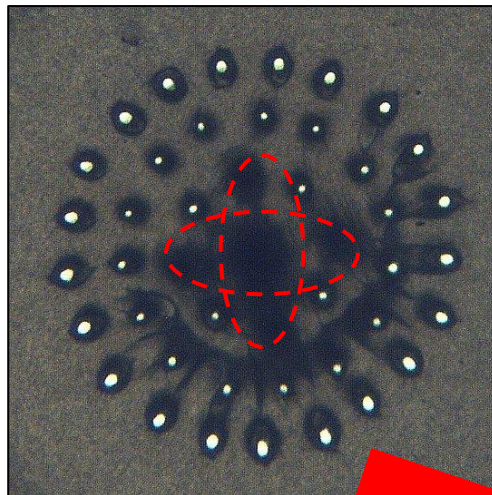




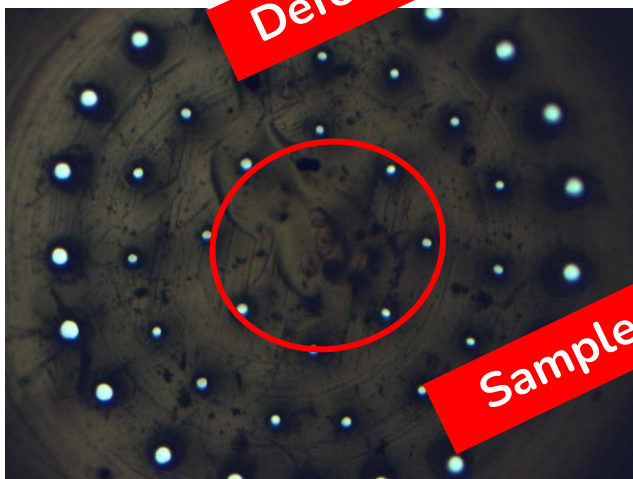
Real-life problems...



Defects in molded polymer



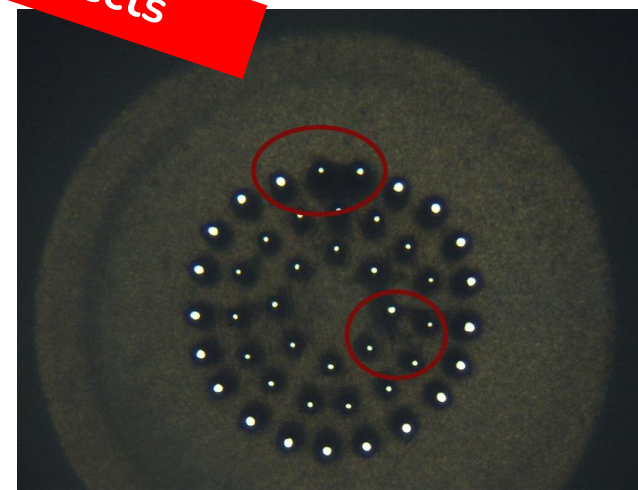
Cross-thermal effects

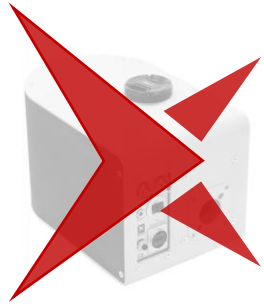


Sample variation from batch to batch



Application economics



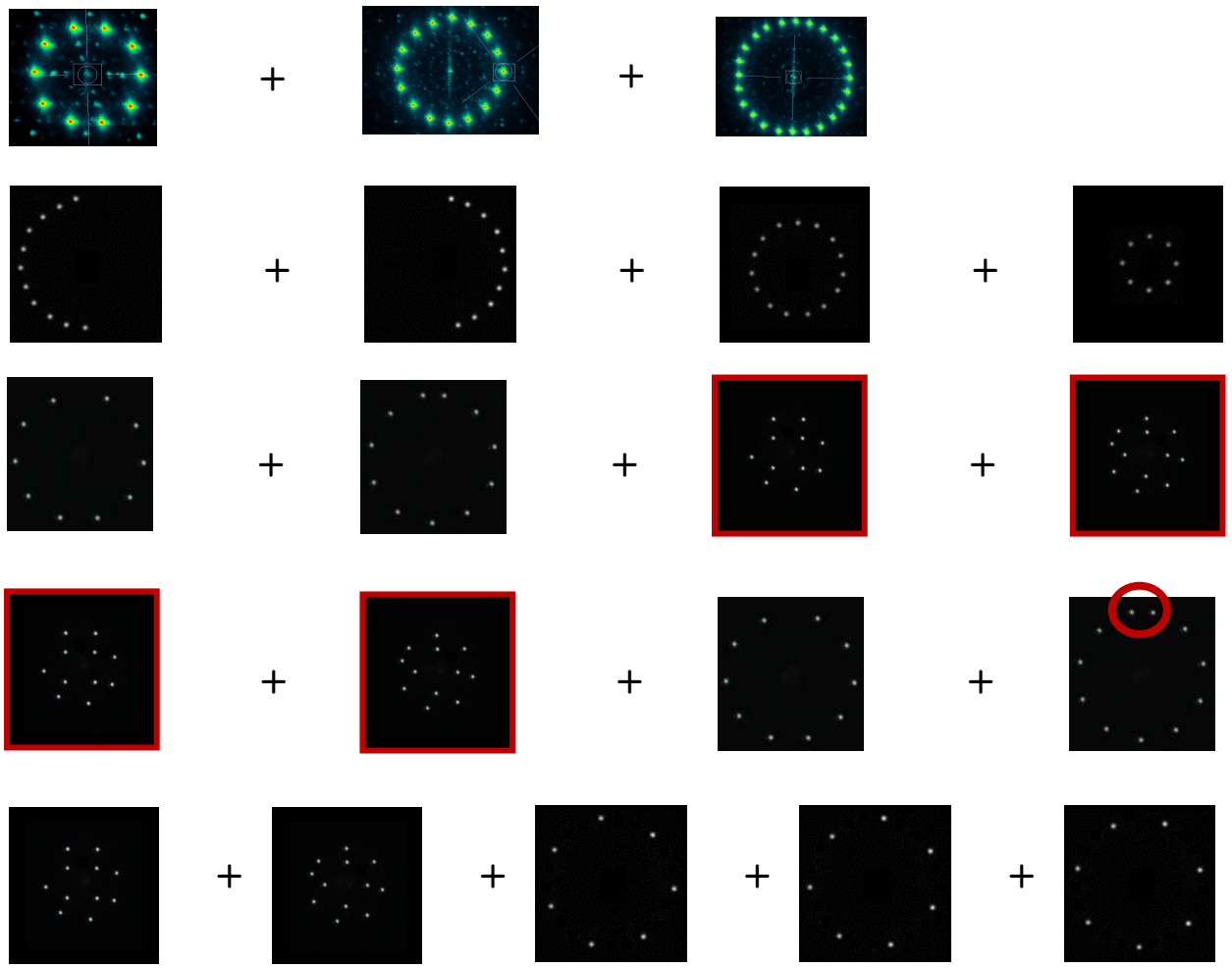


... solved with 'laser brush' optimisation

Initial step



Final step



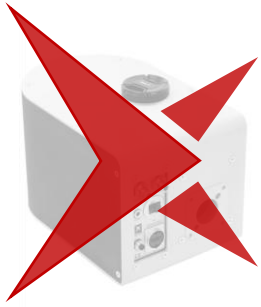
Why?

Use cheaper laser with less energy

Increase distance between beams to lower local heat deposition

Switch sequences to minimize cross-thermal effects in the center where holes density is higher

Add one step to unlock quality bottleneck, given chosen polymer behavior vs thermal effects



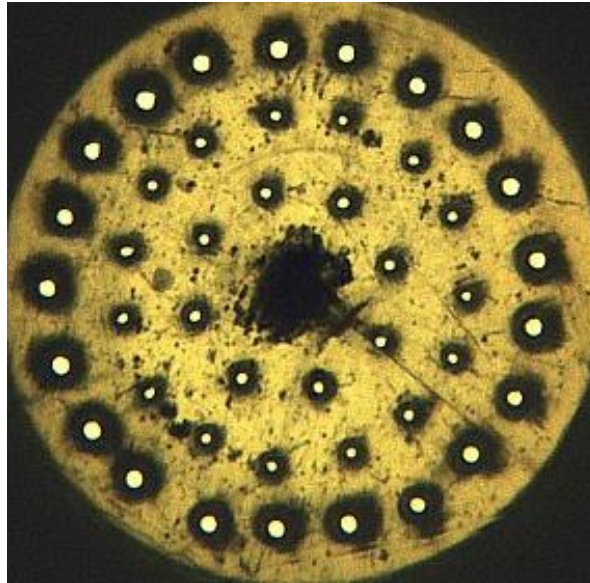
Before vs after

12 units sample set

0,9s/unit

$\Delta_1 = 3,86\mu\text{m}$

$\Delta_2 = 5,22\mu\text{m}$

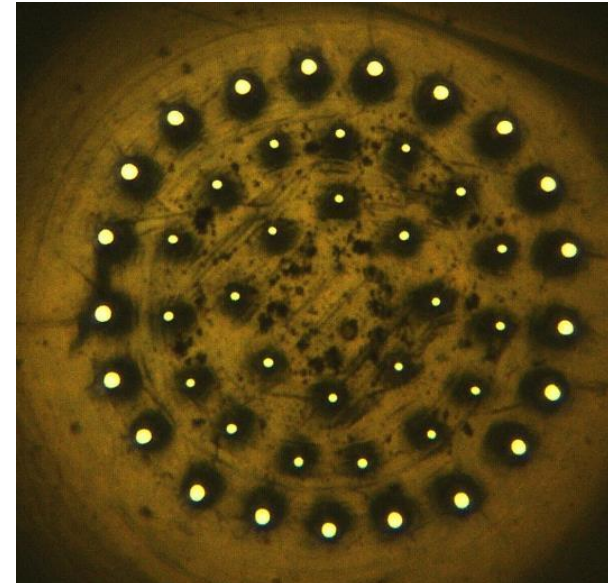


50 units sample set

0,58s/unit

$\Delta_1 = 1,68\mu\text{m}$

$\Delta_2 = 1,75\mu\text{m}$



From end-customer perspective

Cost divided by 8 compared to actual: 780€/ooo → 90€/ooo

Throughput: 90 parts per min with one single laser drilling system

Agility: technically validated new design in < 1weeks

Simplicity: customer fully autonom in a couple weeks, intern level

Thank you for your trust !

**If you have any questions, we
will be happy to answer them.**

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